



Data Sheet

NVIDIA C51M

Mobile Integrated Graphics Processor

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PLATFORM PROCESSORS

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About this Document

This document is targeted to motherboard designers and is intended to provide them with the information necessary to design an NVIDIA® C51M motherboard. It contains a features list, signal description, signal states, power sequencing and RESET information, package information, AC/DC specifications, and the ball map. The information contained in this data sheet is preliminary and subject to change. Please contact your local NVIDIA Sales representative for the latest information.

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Chapter 1.

Introduction to the C51M

The NVIDIA® C51M is the notebook industry's first solution for providing enthusiast-class graphics features, a dedicated video processor with integrated dual channel LVDS or dual channel TMDS and HDTV encoders, and power management features within the budget of every notebook and slim form factor desktop consumer. Paired with either an AMD Opteron, Turion 64, Mobile Athlon 64, or Sempron CPU and an MCP51 media communications processor all the key features needed for computing, displaying, storing, and communicating information come together in notebooks and slim form factor desktops using the C51M.

Product Overview

The NVIDIA C51M includes the following features:

- ❑ Integrated Programmable Shader model 3.0 DirectX 9 graphics processor
 - Shader model 3.0 vertex processor
 - Shader model 3.0 pixel processor
 - CineFX 3.0
 - Intellisample AA
- ❑ Programmable NVIDIA® PureVideo™ processor
- ❑ Integrated dual channel LVDS interface for notebook LCD panels or integrated dual channel TMDS interface for DVI monitors
- ❑ Integrated high definition TV encoder
- ❑ Integrated 300 MHz DAC for external desktop displays
- ❑ Primary HyperTransport link up to 800 MHz to the CPU
- ❑ Secondary HyperTransport link up to 800 MHz
- ❑ PCI Express 16 lane link interface for external graphics processors
- ❑ Dual PCI Express single lane link interface with dedicated controller for ExpressCard and other peripherals
- ❑ Active power management
- ❑ Programmable clock synthesizer
- ❑ 25 mm × 25 mm, 1.0 mm ball pitch PBGA

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Based on the award winning NVIDIA nForce4 and the GeForce 6 series of processors, the C51M represents the next level of integration by combining a graphics processor in a small, low power, space efficient package ideal for desktops and thin light notebooks.

System and Block Diagram

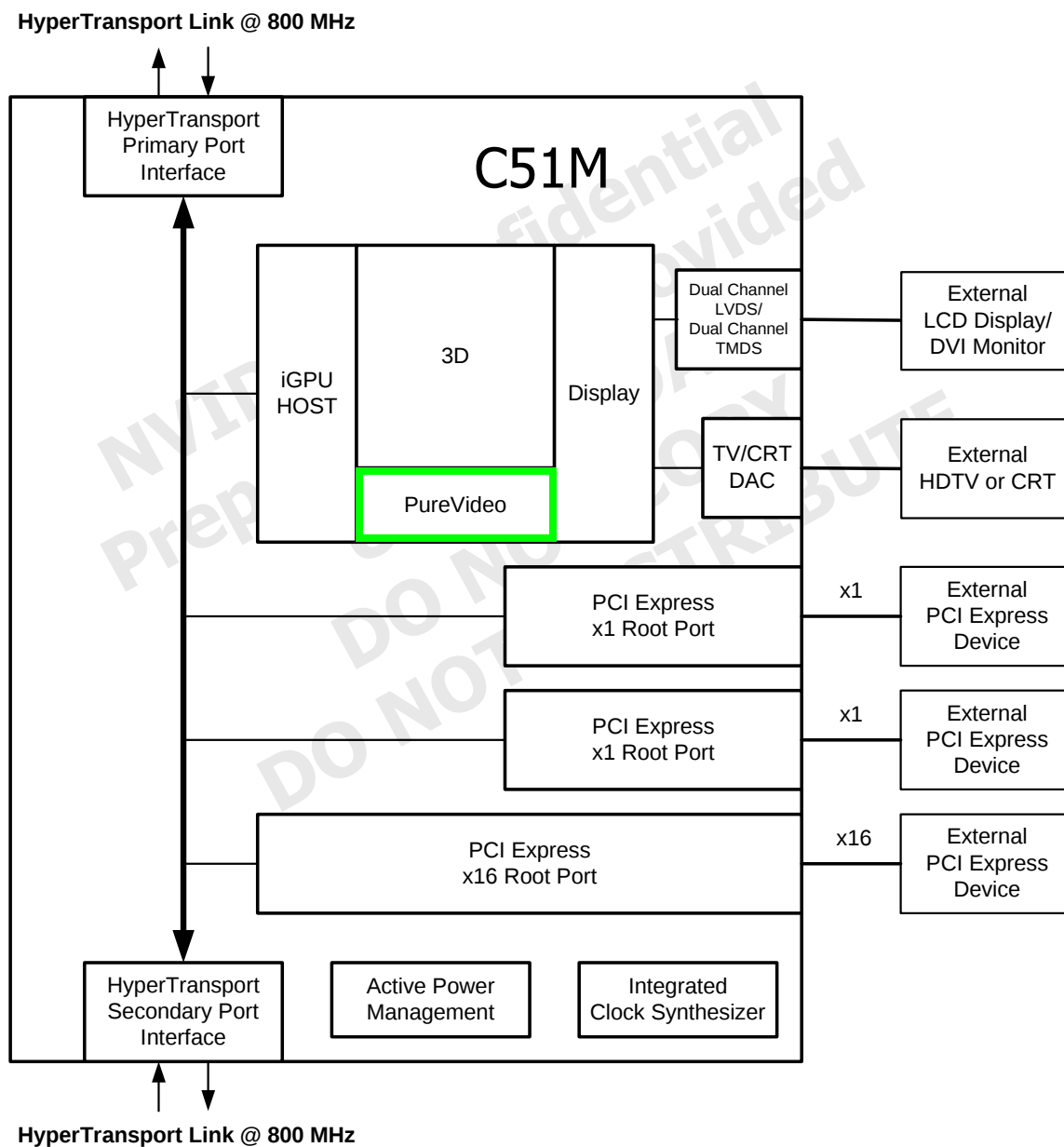


Figure 1. System and Block Diagram

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Features and Functions

Primary HyperTransport Link (to CPU)

- ❑ High-speed, differential, low voltage interface
- ❑ Communication with the AMD Opteron, Turion 64, Mobile Athlon 64, or Sempron CPUs
- ❑ $\times 8$ and $\times 16$ upstream and $\times 8$ and $\times 16$ downstream data paths
- ❑ Up to 800 MHz, for a total bandwidth of up to 6.4 GT/s
- ❑ Supports coherent and non-coherent data types
- ❑ Supports isochronous and non-isochronous data channels
- ❑ Supports real-time link reconnect/disconnect
- ❑ Clock spread spectrum capability

PCI Express Interface

- ❑ Three separate PCI Express controllers with 18 total lanes, configured as one $\times 16$ and two $\times 1$ PCI Express lanes
- ❑ Each controller can support isochronous data
- ❑ WAKE# function is supported for power management
- ❑ 2.5 GHz support, for a total bandwidth of 2.5 Gb/s per direction per lane
- ❑ Clock spread spectrum capability

DirectX 9.0c Shader Model 3.0 Graphics Processing Unit

- ❑ CineFX 3.0 Shading Architecture
 - Vertex Shaders
 - ❖ Supports Microsoft DirectX 9.0 Vertex Shader 3.0
 - ❖ Displacement mapping
 - ❖ Geometry instancing
 - ❖ Infinite length vertex programs
 - Pixel Shaders
 - ❖ Supports DirectX 9.0 Pixel Shader 3.0
 - ❖ Full pixel branching support
 - ❖ Supports Multiple Render Targets (MRTs)
 - ❖ Infinite length pixel programs
 - GeForce6-Class Texture Engine
 - ❖ Up to 16 textures per rendering pass
 - ❖ Supports 16-bit floating point format and 32-bit floating point format
 - ❖ Supports non-power of two textures
 - ❖ Supports sRGB texture format for gamma textures
 - ❖ DirectX and S3TC texture compression

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- ❖ Full 128-bit studio-quality floating point precision through the entire rendering pipeline with native hardware support for 32bpp, 64bpp, and 128bpp rendering modes
- ❑ Intellisample 3.0 Technology2
 - Advanced 16× anisotropic filtering
 - Blistering-fast antialiasing and compression performance
 - New rotated-grid antialiasing removes jagged edges for incredible edge quality
 - Supports advanced lossless compression algorithms for color, texture, and z-data, at even higher resolutions and frame rates
 - Fast z-clear
- ❑ NVIDIA® UltraShadow™ II technology; designed to enhance the performance of shadow-intensive games, like id Software Doom 3
- ❑ Advanced thermal management and thermal monitoring

Programmable PureVideo Processor

- ❑ Sixteen-way VLIW SIMD vector processor
- ❑ Separate scaling controller and coefficient generator
- ❑ Fifty new dedicated video instructions
- ❑ Up to 96 operations per clock
- ❑ MPEG video decode
- ❑ WMV9 decode acceleration
- ❑ Advanced adaptive de-interlacing
- ❑ High-quality video scaling and filtering
- ❑ Hardware accelerated MPEG-2 decoding
- ❑ Microsoft Video Mixing Renderer (VMR) supports multiple video windows with full video quality and features in each window

Display Controller

- ❑ Full NVIDIA® nView™ multi-display technology capability, with independent display controllers for the CRT/TV and LVDS/TMDs interfaces
- ❑ Each controller can drive same or different display contents to different resolutions and refresh rates

Video Mixing Rendered (VMR) Scaling Pipeline

- ❑ Four-tap horizontal by five-tap vertical scaling
- ❑ Arbitrary number of video streams can be scaled simultaneously, each with its own scaling coefficients
- ❑ Scaled output can be directed to overlay, display, or FB for compositing

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Integrated Flat Panel Interface, Dual Channel LVDS Mode

- ❑ Up to SXGA resolution single channel support (135 MHz @ 75 Hz)
 - Four low voltage differential and high speed data channels
 - One low voltage and differential clock channel
- ❑ Up to QXGA resolution dual channel support (266 MHz @ 60 Hz)
 - Eight low voltage differential and high speed data channels
 - Two low voltage and differential clock channels
- ❑ Support for 18-bit and 24-bit notebook LCD panels
- ❑ Clock spread spectrum capability

Integrated Flat Panel Interface, TMDS Mode

- ❑ Up to UXGA resolution single channel support (165 MHz @ 60Hz)
 - Three low voltage, differential data channels at up to 1.65 Gb/s
 - One low voltage differential clock channel at up to 165 MHz
- ❑ Up to 330 MHz dual channel support
 - Six low voltage differential data channels at up to 3.3 Gb/s
 - Two low voltage differential clock channel at up to 330 MHz

Integrated DAC CRT Mode

- ❑ 300 MHz RAMDAC for display resolutions up to and including 1920 × 1440 at 75 Hz
- ❑ Individual RGB 10-bit DACs

Integrated DAC SD/HDTV Encoder Mode

- ❑ Supports HD resolutions, 720p and 1080i
- ❑ RCA, S-video, component output support
- ❑ Support for Japanese D connector
- ❑ Requires 27.0 MHz crystal connected to C51M

Secondary HyperTransport Link

- ❑ High-speed, differential, low voltage interface
- ❑ ×8 and ×16 upstream and ×8 and ×16 downstream data paths
- ❑ Up to 800 MHz operation
- ❑ Supports coherent and non-coherent data types
- ❑ Supports isochronous and non-isochronous data channels
- ❑ Supports real-time link reconnect/disconnect
- ❑ Clock spread spectrum capability

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Integrated Clock Synthesizer

- ❑ Generates all necessary internal and external clock frequencies
 - Based on a single 25 MHz reference clock input from the MCP51
 - Generates clocks for HyperTransport link, PCI Express, AMD Opteron, Turion 64, Mobile Athlon 64, or Sempron CPUs
- ❑ Spread spectrum capable on the following clocks: CPU + upstream HyperTransport link, PCI Express, and downstream HyperTransport link clocks
- ❑ Simplifies system design and motherboard layout

System and Power Management

Power Management

- ❑ Supports instantly available PC (IAPC), ACPI 2.0, and PCI PM 1.1
- ❑ PME message support on PCI Express links
- ❑ Active clock generator management
- ❑ Active clock tree gating and PLL power-down
- ❑ Integrated thermal sensor
- ❑ Thermal event detection (alarm)
- ❑ Power On Suspend (POS) or ACPI S1 support
- ❑ Suspend to RAM (STR) or ACPI S3 support
- ❑ Suspend to Disk (STD) or ACPI S4/S5 support
- ❑ Supports C0, C1, C2, and C3 states
- ❑ Supports HyperTransport link disconnect and STOP/REQ protocol
- ❑ Supports FID/VID cycles for CPU P-state transition and AMD Cool'n'Quiet

Chapter 2. Signal Descriptions

This chapter contains the signal descriptions for the NVIDIA C51M. See Appendix A for signal listings by ball location and signal name and Appendix B for the ballout.

This chapter contains the following information:

- ❑ Conventions
- ❑ Primary HyperTransport Interface to the CPU
- ❑ Secondary HyperTransport Interface
- ❑ PCI Express Interface
- ❑ Integrated Dual Channel LVDS Transmitter Interface
- ❑ Integrated Dual Channel TMDS Transmitter Interface
- ❑ Video DAC Signals
- ❑ Power Supply
- ❑ Clocks
- ❑ TEST/JTAG Interface

PROPRIETARY INFORMATION

Conventions

Following are the conventions used in describing the signals for the NVIDIA C51M:

❑ **Signal Names**

Signal names use a mnemonic to represent the function of the signal. Active low single-ended signals are identified by a pound sign (#) after the signal name. Active high signals do not have the pound sign (#) after the signal names. Differential signals have _P (positive) or _N (complementary) suffixes to indicate the polarity within the pair.

❑ **I/O Type**

The signal I/O type is represented as a code to indicate the operational characteristics of the signal. Table 1 lists the I/O codes used in the signal description tables.

Table 1. Signal Type Codes

Item	Description
A	Analog
DIFF I/O	Differential input/output
DIFF IN	Differential input
DIFF OUT	Differential output
I	Input
I/O	Bidirectional input/output
O	Output
OC	Open collector output
OD	Open drain output
P	Power

Note: Signals can be part of more than one interface.

PROPRIETARY INFORMATION

Primary HyperTransport Interface to the CPU

Table 2. Primary HyperTransport Interface Signals to the CPU

Signal	I/O	Definition
HT_CPU_REQ#	I	HyperTransport Link Request This asynchronous signal indicates that an external master wishes to send a transaction and the HyperTransport link should be reconnected. This signal should be an input tied to a motherboard pull-up. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_CPU_RX_CLK[1:0]_P HT_CPU_RX_CLK[1:0]_N	DIFF IN	HyperTransport Link Differential Receive Clocks These signals are the differential pairs used as the timing reference for HT_CPU_RXD[15:0] and HT_CPU_RXCTL. HT_CPU_RX_CLK1_P/HT_CPU_RX_CLK1_N is used for HT_CPU_RXD[15:8] and HT_CPU_RX_CLK0_P/HT_CPU_RX_CLK0_N is used for HT_CPU_RXD[7:0] and HT_CPU_RXCTL. When interfacing to a link width smaller than the full 16 bits, please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for more details.
HT_CPU_RXCTL_P HT_CPU_RXCTL_N	DIFF IN	HyperTransport Link Differential Receive Control Receive link control signal.
HT_CPU_RXD[15:0]_P HT_CPU_RXD[15:0]_N	DIFF IN	HyperTransport Link Differential Receive Data These signals are the differential pairs used to receive the high-speed 16 bits of information from the upstream CPU. The C51M supports HyperTransport link widths of 8 and 16 bits. When interfacing to a link width smaller than the full 16-bits, please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for more details.
HT_CPU_STOP#	OD	HyperTransport Link Disconnect This signal enables and disables the HyperTransport link during system state transitions. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_CPU_TX_CLK[1:0]_P HT_CPU_TX_CLK[1:0]_N	DIFF OUT	HyperTransport Link Differential Transmit Clocks These signals are the differential pairs used as the timing reference for HT_CPU_TXD[15:0] and HT_CPU_TXCTL. HT_CPU_TX_CLK1_P/HT_CPU_TX_CLK1_N is used for HT_CPU_TXD[15:8] and HT_CPU_TX_CLK0_P/HT_CPU_TX_CLK0_N is used for HT_CPU_TXD[7:0] and HT_CPU_TXCTL. These clock pairs are spread spectrum capable for EMI reduction. When interfacing to a link width smaller than the full 16 bits, please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for more details.
HT_CPU_TXCTL_P HT_CPU_TXCTL_N	DIFF OUT	HyperTransport Link Differential Transmit Control Transmit link control signal.
HT_CPU_TXD[15:0]_P HT_CPU_TXD[15:0]_N	DIFF OUT	HyperTransport Link Differential Transmit Data These signals are the differential pairs used to transmit the high-speed 16 bits of information to the upstream CPU. The C51M supports HyperTransport link widths of 8 and 16 bits. When interfacing to a link width smaller than the full 16-bits, please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for more details.

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Signal	I/O	Definition
HT_CPU_PWRGD	OD	CPU Power OK This signal is the Power Good/Cold Reset control for the upstream HyperTransport device. Typically this connects to an AMD Opteron, Turion 64, Mobile Athlon 64, or Sempron CPU. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_CPU_RST#	OD	CPU Reset This signal is the warm reset signal control for the upstream HyperTransport device. Typically this connects to an AMD Opteron, Turion 64, Mobile Athlon 64, or Sempron CPU. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_CPU_CAL_1P2V	A	HyperTransport Calibration Used for HyperTransport link interface pads calibration. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_CPU_CAL_GND	A	HyperTransport Calibration Used for HyperTransport link interface pads calibration. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .

Secondary HyperTransport Interface

Table 3. Secondary HyperTransport Interface Signals

Signal	I/O	Definition
HT_MCP_REQ#	OD	HyperTransport Link Request This asynchronous signal indicates that a master, internal to the C51M, wishes to send a transaction and the HyperTransport link should be reconnected. C51M asserts this signal when its Primary or Secondary links have a transaction pending irrespective of the current link state. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_MCP_RX_CLK[1:0]_P HT_MCP_RX_CLK[1:0]_N	DIFF IN	HyperTransport Link Differential Receive Clocks These signals are the differential pairs used as the timing reference for HT_MCP_RXD[15:0] and HT_MCP_RXCTL. HT_MCP_RX_CLK1_P/HT_MCP_RX_CLK1_N is used for HT_MCP_RXD[15:8] and HT_MCP_RX_CLK0_P/HT_MCP_RX_CLK0_N is used for HT_MCP_RXD[7:0] and HT_MCP_RXCTL. When interfacing to a link width smaller than the full 16 bits, please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_MCP_RXCTL_P HT_MCP_RXCTL_N	DIFF IN	HyperTransport Link Differential Receive Control Receive link control signal.
HT_MCP_RXD[15:0]_P HT_MCP_RXD[15:0]_N	DIFF IN	HyperTransport Link Differential Receive Data These signals are the differential pairs used to receive the high-speed 16 bits of information from the downstream MCP51. The C51M supports HyperTransport link widths of 8 and 16 bits. When interfacing to a link width smaller than the full 16-bits, please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .

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Signal	I/O	Definition
HT_MCP_STOP#	I	HyperTransport Link Disconnect This signal enables and disables the HyperTransport link during system state transitions. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_MCP_TX_CLK[1:0]_P HT_MCP_TX_CLK[1:0]_N	DIFF OUT	HyperTransport Link Differential Transmit Clocks These signals are the differential pairs used as the timing reference for HT_MCP_TXD[15:0] and HT_MCP_TXCTL. HT_MCP_TX_CLK1_P/HT_MCP_TX_CLK1_N is used for HT_MCP_TXD[15:8] and HT_MCP_TX_CLK0_P/HT_MCP_TX_CLK0_N is used for HT_MCP_TXD[7:0] and HT_MCP_TXCTL. These clock pairs are capable of tracking a spread spectrum input reference for EMI reduction. When interfacing to a link width smaller than the full 16 bits, please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_MCP_TXCTL_P HT_MCP_TXCTL_N	DIFF OUT	HyperTransport Link Differential Transmit Control Transmit link control signal.
HT_MCP_TXD[15:0]_P HT_MCP_TXD[15:0]_N	DIFF OUT	HyperTransport Link Differential Transmit Data These signals are the differential pairs used to transmit the high-speed 16 bits of information to the downstream HyperTransport device. The C51M supports HyperTransport link widths of 8 and 16 bits. When interfacing to a link width smaller than the full 16-bits, please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_MCP_PWRGD	I	MCP Power OK This signal is the Power Good/Cold Reset control for the upstream HyperTransport device. Typically this connects to the C51M. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_MCP_RESET#	I	MCP Reset This signal is the warm reset signal control for the upstream HyperTransport device. Typically this connects to the MCP51. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_MCP_CAL_1P2V	A	HyperTransport Calibration Used for HyperTransport Link interface pads calibration. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
HT_MCP_CAL_GND	A	HyperTransport Calibration Used for HyperTransport Link interface pads calibration. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .

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PCI Express Interface

Table 4. PCI Express x16 Interface Signals

Signal	I/O	Definition
PE0_PRSENT#	I	PCI Express x16 Presence Detect This signal is the presence/hot plug presence detect of a device on the x16 PCI Express link.
PE0_REFCLK_P PE0_REFCLK_N	DIFF OUT	PCI Express x16 Reference Clock These signals are the 100 MHz differential reference clock pair for the x16 PCI Express link.
PE0_RX[15:0]_P PE0_RX[15:0]_N	DIFF IN	PCI Express x16 Receive Data These signals are the x16 differential receive data pairs of the PCI Express link.
PE0_TX[15:0]_P PE0_TX[15:0]_N	DIFF OUT	PCI Express x16 Transmit Data These signals are the x16 differential transmit data pairs of the PCI Express link.

Table 5. PCI Express1 x1 Interface Signals

Signal	I/O	Definition
PE1_CLKREQ#	I	PCI Express x1 Reference Clock Request This signal is used by a PCI Express device to indicate it needs the PE1_REFCLK_P and PE1_REFCLK_N to actively drive the 100 MHz reference clock.
PE1_PRSENT#	I	PCI Express x1 Presence Detect This signal is the hot plug presence detect of a device on a x1 PCI Express link.
PE1_REFCLK_P PE1_REFCLK_N	DIFF OUT	PCI Express x1 Reference Clock These signals are the 100 MHz differential reference clock pair for the first x1 PCI Express link.
PE1_RX_P PE1_RX_N	DIFF IN	PCI Express x1 Receive Data These signals are the x1 differential receive data pair of the first x1 PCI Express link.
PE1_TX_P PE1_TX_N	DIFF OUT	PCI Express x1 Transmit Data These signals are the x1 differential transmit data pair of the first x1 PCI Express link.

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Table 6. PCI Express2 x1 Interface Signals

Signal	I/O	Definition
PE2_CLKREQ#	I	PCI Express x1 Reference Clock Request This signal is used by a PCI Express device to indicate it needs the PE2_REFCLK_P and PE2_REFCLK_N to actively drive the 100 MHz reference clock.
PE2_PRSENT#	I	PCI Express x1 Presence Detect This signal is the hot plug presence detect of a device on a ×1 PCI Express link.
PE2_REFCLK_P PE2_REFCLK_N	DIFF OUT	PCI Express x1 Reference Clock These signals are the 100 MHz differential reference clock pair for the second ×1 PCI Express link.
PE2_RX_P PE2_RX_N	DIFF IN	PCI Express x1 Receive Data These signals are the ×1 differential receive data pair of the second ×1 PCI Express link.
PE2_TX_P PE2_TX_N	DIFF OUT	PCI Express x1 Transmit Data These signals are the ×1 differential transmit data pair of the second ×1 PCI Express link.

Table 7. PCI Express Interface Signals

Signal	I/O	Definition
PE_RESET#	I	PCI Express Reset This signal is used Reset PCI Express links.
PE_CTERM_GND	A	PCI Express Termination Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
PE_REFCLKIN_N PE_REFCLKIN_P	DIFF IN	PCI Express Reference Clock Input These signals are the 100 MHz differential reference clock pair input for the PCI Express link.
PE_TSTCLK_N PE_TXTCLK_P	DIFF OUT	PCI Express Test Clock Output These signals are the differential test clock pair of the PCI Express link.

PROPRIETARY INFORMATION

Integrated Flat Panel Transmitter Dual Channel LVDS Mode

In LVDS mode, the **+2.5V_IFPA** and **+2.5V_IFPB** can be either +2.5V or +3.3V.

Table 8. Integrated Dual Channel LVDS Transmitter Interface

Signal	I/O	Description
IFPAB_RSET	A	Reference Current Produces a reference current through an external resistor. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for the appropriate value and tolerance.
IFPA_TXD[3:0]_P IFPA_TXD[3:0]_N	DIFF OUT	LVDS Low-Voltage Differential Single Channel Data Low voltage differential and high speed single channel data outputs.
IFPA_TXC_P IFPA_TXC_N	DIFF OUT	LVDS Low-Voltage Differential Clock for IFPA_TXD[3:0] Low voltage differential single channel output clock used for IFPA_TXD[3:0] .
IFPB_TXD[7:4]_P IFPB_TXD[7:4]_N	DIFF OUT	LVDS Low-Voltage Differential Dual Channel Data Low voltage differential and high speed dual channel data outputs.
IFPB_TXC_P IFPB_TXC_N	DIFF OUT	LVDS Low-Voltage Differential Clock for IFPB_TXD[7:4] Low voltage differential dual channel output clock used for IFPB_TXD[7:4] .

Note: The DDC and panel sequencing interface for the integrated GPU flat panel interface are connected to the MCP51 component.

The integrated LVDS channel supports LVDS/OpenLDI-compliant LCD panels. It supports 18-bit or 24-bit, single-pixel or dual-pixel mode panels, either balanced or unbalanced. Single channel panels use only IFPA signals while dual channel LVDS panels use both IFPA and IFPB signals.

Table 9 and Table 10 detail how the video data are mapped to the LVDS channel signals in “unbalanced” mode. Table 11 and Table 12 detail how the video data are mapped to the LVDS channel signals in “balanced” mode. For more details, refer to the *OpenLDI Specification* published by National Semiconductor.

Note: Tables 9 through 12 assume Channel A is used to drive the LCD panel in single-pixel mode.

Table 9. 18-Bit Single-Pixel Mode, Unbalanced

	Bit	Bit	Bit	Bit	Bit	Bit	Bit
--	-----	-----	-----	-----	-----	-----	-----

PROPRIETARY INFORMATION

	time0	time1	time2	time3	time4	time5	time6
IFPA_TXD0	G0	R5	R4	R3	R2	R1	R0
IFPA_TXD1	B1	B0	G5	G4	G3	G2	G1
IFPA_TXD2	DE	VSYNC	HSYNC	B5	B4	B3	B2
IFPA_TXD3							

Table 10. 24-Bit Single-Pixel Mode, Unbalanced

	Bit time0	Bit time1	Bit time2	Bit time3	Bit time4	Bit time5	Bit time6
IFPA_TXD0	G0	R5	R4	R3	R2	R1	R0
IFPA_TXD1	B1	B0	G5	G4	G3	G2	G1
IFPA_TXD2	DE	VSYNC	HSYNC	B5	B4	B3	B2
IFPA_TXD3	Reserved	B7	B6	G7	G6	R7	R6

Table 11. 18-Bit Dual-Pixel Mode, Unbalanced

	Bit time0	Bit time1	Bit time2	Bit time3	Bit time4	Bit time5	Bit time6
IFPA_TXD0	GU0	RU5	RU4	RU3	RU2	RU1	RU0
IFPA_TXD1	BU1	BU0	GU5	GU4	GU3	GU2	GU1
IFPA_TXD2	DE	VSYNC	HSYNC	BU5	BU4	BU3	BU2
IFPA_TXD3							
IFPB_TXD4	GL0	RL5	RL4	RL3	RL2	RL1	RL0
IFPB_TXD5	BL1	BL0	GL5	GL4	GL3	GL2	GL1
IFPB_TXD6	Reserved	CNTLE	CNTLE	BL5	BL4	BL3	BL2
IFPB_TXD7							

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Table 12. 24-Bit Dual-Pixel Mode, Unbalanced

	Bit time0	Bit time1	Bit time2	Bit time3	Bit time4	Bit time5	Bit time6
IFPA_TXD0	GU0	RU5	RU4	RU3	RU2	RU1	RU0
IFPA_TXD1	BU1	BU0	GU5	GU4	GU3	GU2	GU1
IFPA_TXD2	DE	VSYNC	HSYNC	BU5	BU4	BU3	BU2
IFPA_TXD3	Reserved	BU7	BU6	GU7	GU6	BU7	BU6
IFPB_TXD4	GL0	RL5	RL4	RL3	RL2	RL1	RL0
IFPB_TXD5	BL1	BL0	GL5	GL4	GL3	GL2	GL1
IFPB_TXD6	Reserved	CNTLE	CNTLE	BL5	BL4	BL3	BL2
IFPB_TXD7	Reserved	BL7	BL6	GL7	GL6	RL7	RL6

Integrated Flat Panel Interface TMDS Mode

In TMDS mode, the **+2.5V_IFPA** and **+2.5V_IFPB** must be **+3.3V**. If TMDS is not used, then it can be either **+2.5V** or **+3.3V**.

Table 13. Integrated Dual Channel TMDS Interface

Signal	I/O	Description
IFPAB_RSET	A	TMDS Low Voltage Output Swing Current Reference This resistor sets the current reference for the output differential voltage swing level on the 6 data channels and 2 clock channel. Please refer to the <i>NVIDIA C51G and MCP51 Design Guide</i> for further information.
IFPA_TXD[2:0]_P IFPA_TXD[2:0]_N	DIFF OUT	Single Channel TMDS Output Data Channel [2:0] These signals are the 3 low voltage, differential, high speed output data signals for single channel TMDS or the first 3 channels in a dual channel TMDS configuration.
IFPA_TXC_P IFPA_TXC_N	DIFF OUT	Single channel TMDS Output Clock Channel This signal is the low voltage differential clock channel output signal for signal channel TMDS or the first clock channel in a dual channel TMDS configuration.
IFPB_TXD[6:4]_P IFPB_TXD[6:4]_N	DIFF OUT	Dual Channel TMDS Output Data Channel [2:0] These signals are the second 3 low voltage, differential, high speed output data signals in a dual channel TMDS configuration.
IFPB_TXC_P IFPB_TXC_N	DIFF OUT	Dual channel TMDS Output Clock Channel This signal is the second low voltage differential clock channel output signal in a dual channel TMDS configuration.

Note: The DDC and panel sequencing interface for the integrated GPU flat panel interface are connected to the MCP51 component.

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Video DAC/TV Out Signals

Table 14. Video DAC/TV Out Signals

Signal	I/O	Description
DAC_RED DAC_GREEN DAC_BLUE Chrominance (DAC_RED) Luminance (DAC_GREEN) Composite (DAC_BLUE) Pr (DAC_RED) Y (DAC_GREEN) Pb (DAC_BLUE)	O	Red, Green, and Blue Outputs These signals are the RGB display monitor outputs. Software configures these signals to drive either a doubly terminated or singly terminated 75-ohm load. TV Chrominance, Luminance, and Composite Outputs These signals are also the S-video analog chrominance and luminance outputs, as well as the standard composite output. HDTV Component Outputs These signals are also the HDTV component outputs. The above TV out signal mapping is the default but is fully programmable. The type of output is determined by an output load detect algorithm. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for the specific application.
DAC_IDUMP	P	DAC Ground Reference Local GND reference for the internal triple DACs.
DAC_HSYNC	I/O	Horizontal Sync Horizontal sync supplied to the display monitor. Output level is 3.3V.
DAC_RSET	A	DAC Reference Current Set A precision resistor placed between this pin and GND sets the full-scale video DAC current. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for the suggested value and tolerance of this resistor.
DAC_VREF	A	DAC Reference Voltage A capacitor should be placed between this pin and GND . Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for the suggested value and tolerance of this capacitor.
DAC_VSYNC	I/O	Vertical Sync Vertical sync supplied to the display monitor. Output level is 3.3V.
XTAL_IN XTAL_OUT	I/O	TV Encoder Reference Clock Input A 27.0 MHz series resonant crystal is connected between these two points to provide the reference clock for the TV Encoder. Alternately, an external LVTTTL clock oscillator output may be driven in on signal XTAL_IN , leaving XTAL_OUT unconnected. If the internal TV Encoder is not used then XTAL_IN should be connected to GND leaving XTAL_OUT unconnected. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for crystal frequency and tolerance.

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Power Supply

Table 15. Power Supply Interface

Signal	I/O	Description
+1.2V_CORE	P	Core Power Rail This voltage powers the core logic of the C51M. It is derived from the main silver box "PS_ON" power supply rails.
+1.2V_HT	P	Isolated HyperTransport Power Rail Since the +1.2V_CORE power rail is enabled simultaneously with the +3.3V main power supply rail and before the CPU power is valid, the enable of this rail must be delayed to honor the AMD power sequence. Most NVIDIA MCP devices have timed digital sequencer outputs. These can be used to accurately control this sequence in accordance with AMD regulations and without using highly variable RC timing circuits.
+1.2V_HTMCP	P	HyperTransport to MCP Power Rail This voltage powers the HyperTransport interface between the C51M and the MCP51. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
+1.2V_PEA	P	+1.2V PCI Express Analog Voltage This is a filtered version of the +1.2V_CORE power supply and is used to power the analog circuits of the PCI Express block. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.
+1.2V_PED	P	+1.2V PCI Express Digital Voltage This is a filtered version of the +1.2V_CORE power supply and is used to power the digital circuits of the PCI Express block. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.
+1.2V_PLL	P	+1.2V PLL Voltage This is a filtered version of the +1.2V_CORE power supply and is used to power some of the internal PLLs. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.
+1.2V_PLLCORE	P	+1.2V Core PLL Voltage This voltage powers the PLL of the core logic. It is a filtered version of the +1.2V_CORE voltage. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.
+1.2V_PLLHTCPU	P	+1.2V CPU HT PLL Voltage This voltage powers the PLL of the HyperTransport interface to the CPU. It is a filtered version of the +1.2V_CORE voltage. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.
+1.2V_PLLHTMCP	P	+1.2V MCP HT PLL Voltage This voltage powers the PLL of the HyperTransport interface to the MCP. It is a filtered version of the +1.2V_CORE voltage. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.

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Signal	I/O	Description
+1.2V_PLLIFP	P	+1.2V IFP PLL Voltage This voltage powers the PLL of the integrated LVDS/TMDS block. It is a filtered version of the +1.2V_CORE voltage. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.
+2.5V_CORE	P	2.5V Core Voltage This voltage is used to power the core logic of the C51M. It is derived from the main silver box "PS_ON" power supply rails.
+2.5V_PLLCORE	P	+2.5V Core PLL Voltage This voltage powers the core PLL. It is a filtered version of the +2.5V_CORE voltage. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.
+2.5V_PLLGPU	P	+2.5V GPU PLL Voltage This voltage powers the PLL of the integrated GPU. It is a filtered version of the +2.5V_CORE voltage. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.
+2.5V_PLLHTCPU	P	+2.5V CPU HT PLL Voltage This voltage powers the PLL of the HyperTransport interface to the CPU. It is a filtered version of the +2.5V_CORE voltage. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.
+2.5V_PLLIFP	P	+2.5V IFP PLL Voltage This voltage powers the PLL of the integrated LVDS/TMDS block. It is a filtered version of the +2.5V_CORE voltage. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.
+3.3V	P	+3.3V Voltage This voltage is the +3.3V rail supplied by the main silver box power supply. It is used to power the +3.3V I/Os.
+3.3V_DAC	P	+3.3V DAC Voltage This voltage power the video output DAC. It is a filtered version of the +3.3V power supply. Refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details on the filter design.
+2.5V_IFPA	P	+2.5V Integrated Single Channel LVDS Voltage This voltage powers the integrated single channel LVDS block. It is a filtered version of the +2.5V_CORE voltage. +3.3V Integrated Single Channel TMDS Voltage This voltage powers the integrated single channel TMDS block. It is a filtered version of the +3.3V voltage. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design. +3.3V Integrated Single Channel TMDS Voltage This voltage powers the integrated single channel TMDS block. It is a filtered version of the +3.3V voltage. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design.

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Signal	I/O	Description
+2.5V_IFPB	P	+2.5V Integrated Dual Channel LVDS Voltage This voltage powers the integrated dual channel LVDS block. It is a filtered version of the +2.5V_CORE voltage. +3.3V Integrated Dual Channel TMDS Voltage This voltage powers the integrated dual channel TMDS block. It is a filtered version of the +3.3V voltage. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> for details of the filter design."
PE_GND	P	Ground
GND	P	Ground

Clocks

Table 16. Clock Signals

Signal	I/O	Description
CLKIN_25MHZ	I	Non-Spread Reference Clock Input Typically, this clock is a buffered version of the 25 MHz crystal from the downstream MCP51. It is used as the reference for the iGPU, PCI Express, and upstream HyperTransport PLLs.
CLKIN_200MHZ_P CLKIN_200MHZ_N	DIFF IN	Clock In 200 MHz This is the reference clock input for the PLL of the downstream HyperTransport link to the MCP51. It is spread spectrum capable.
CLKOUT_PRI_200MHZ_P CLKOUT_PRI_200MHZ_N CLKOUT_SEC_200MHZ_P CLKOUT_SEC_200MHZ_N	DIFF OUT	Clock Out 200 MHz These spread-spectrum capable differential clock outputs provide the HT reference inputs to the CPUs and other HT devices in the system. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
SCLKIN_MCLKOUT_200MHZ_P SCLKIN_MCLKOUT_200MHZ_N	DIFF I/O	Clock Out 200 MHz These signals are outputs and behave identically to the CLKOUT_PRI_200MHZ/CLKOUT_SEC_200MHZ signal pairs.
CLKOUT_CTERM_GND	A	200 MHz Clock Out Termination Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .

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TEST/JTAG Interface

Table 17. TEST Interface Signals

Signal	I/O	Description
IFPAB_VPROBE	A	This should be left as a no connect. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
TEST_MODE_EN	I	This pin may be connected directly to GND . Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
PKG_TEST	I	This signal is pulled down to GND for normal operations. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
JTAG_TCK	I	JTAG Clock This signal must be pulled down to GND through a resistor for normal operation. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
JTAG_TDI	I	JTAG Serial Data Input This signal must be pulled up to +3.3 V through a resistor for normal operation. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
JTAG_TDO	O	JTAG Serial Data Output This signal must be left as a no-connect for normal operation. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
JTAG_TMS	I	JTAG Mode Select This signal must be pulled up to +3.3 V through a resistor for normal operation. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .
JTAG_TRST#	I	JTAG Reset This signal must be pulled down to GND through a resistor for normal operation. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .

No Connect Interface

Table 18. No Connect Interface Signals

Signal	Description
NC	These signals should be left as a no-connect for normal operation. Please refer to the <i>NVIDIA C51 and MCP51 Design Guide</i> .

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Chapter 3. Clock Domains

Clocking

Figure 2 shows the clocks that are used or generated by the NVIDIA C51M to and from the various peripherals. Table 19 lists the signals.

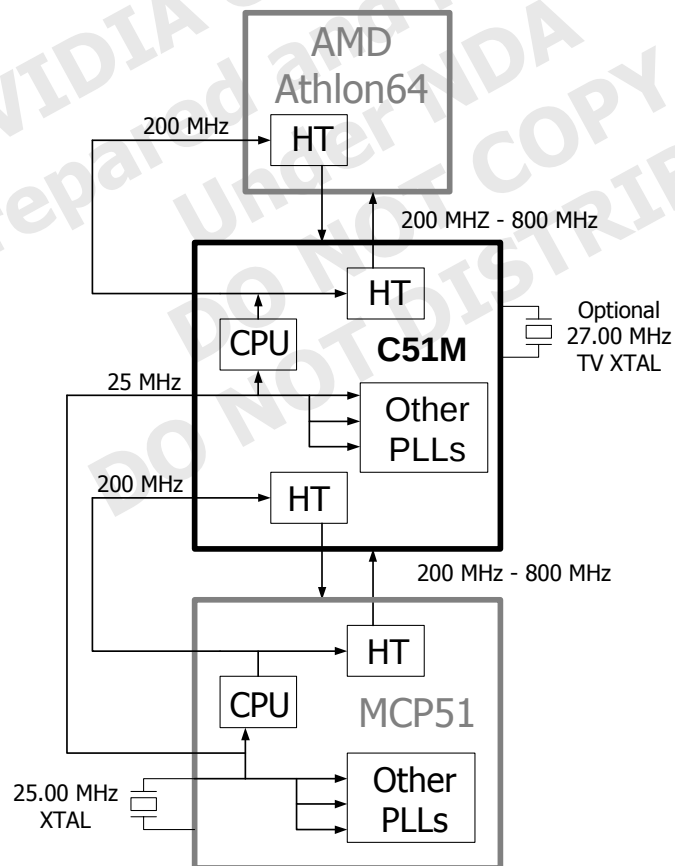


Figure 2. Simple Clock Block Diagram

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Table 19. Clock Signals

Clock Signal	Frequency (in MHz unless noted)	I/O	Description
HT_CPU_TX_CLK[1:0]	Variable 200 – 800	DIFF OUT	HyperTransport Link Differential Transmit Clocks These clocks are used to synchronize the transmission of data to the upstream CPU.
HT_CPU_RX_CLK[1:0]	Variable 200 - 800	DIFF IN	HyperTransport Link Differential Receive Clocks These clocks are used to synchronize the reception of data from the upstream CPU.
HT_MCP_TX_CLK[1:0]	Variable 200 – 800	DIFF OUT	HyperTransport Link Differential Transmit Clocks These clocks are used to synchronize the transmission of data to the downstream MCP.
HT_MCP_RX_CLK[1:0]	Variable 200 - 800	DIFF IN	HyperTransport Link Differential Receive Clocks These clocks are used to synchronize the reception of data from the downstream MCP.
PE[2:0]_REFCLK	100	DIFF OUT	PCI Express Reference Clocks These are the 100 MHz differential reference clock pairs for the x1 and x16 PCI Express links.
IFPA_TXC	Variable	DIFF OUT	Single Channel LVDS/TMFDS Interface Differential Clocks These are the Single Channel LVDS/TMDS interface low-voltage differential clocks that drive the flat panel.
IFPB_TXC	Variable	DIFF OUT	Dual Channel LVDS/TMFDS Interface Differential Clocks These are the Dual Channel LVDS/TMDS interface low-voltage differential clocks that drive the flat panel.
XTAL_IN XTAL_OUT	27.0	I/O	TV Encoder Crystal This crystal oscillator generates the timing base for the optional TV encoder.
CLKIN_25MHZ	25.0	I	25 MHz Clock In This is the non-spread reference clock input. Typically this clock is a buffered version of the 25 MHz crystal from the downstream MCP51. It is used as the reference for the iGPU, PCI Express, and upstream HyperTransport PLLs.
CLKIN_200MHZ	200	DIFF IN	Clock In 200 MHz This is the spread-spectrum capable reference input clock for the PLL of the downstream HyperTransport link to the MCP.
CLKOUT_PRI_200MHZ CLKOUT_SEC_200MHZ	200	DIFF OUT	Clock Out 200 MHz These spread-spectrum capable differential clock outputs provide the HyperTransport reference inputs to the CPUs and other HyperTransport devices in the system.

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Clock Signal	Frequency (in MHz unless noted)	I/O	Description
SCLKIN_MCLKOUT_200MHZ	200	DIFF I/O	Clock Out 200 MHz This becomes an output clock which behaves identically to the CLKOUT_PRI_200MHZ/CLKOUT_SEC_200MHZ signals.
PE_REFCLKIN	100	DIFF IN	PCI Express Reference Clock Input These signals are the 100 MHz differential reference clock pair input for the PCI Express link.
PE_TSTCLK	100	DIFF OUT	PCI Express Test Clock Output These signals are the differential test clock pair of the PCI Express link.
JTAG_TCK	Variable	I	JTAG Clock This signal must be pulled down to GND through a resistor for normal operation.

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Chapter 4. Power Sequencing and Reset

Power Sequencing and Reset Information

Please refer to the *NVIDIA C51 and MCP51 Design Guide* as a lot of information pertaining to the Power Sequencing and RESET are dependent upon motherboard design implementations.

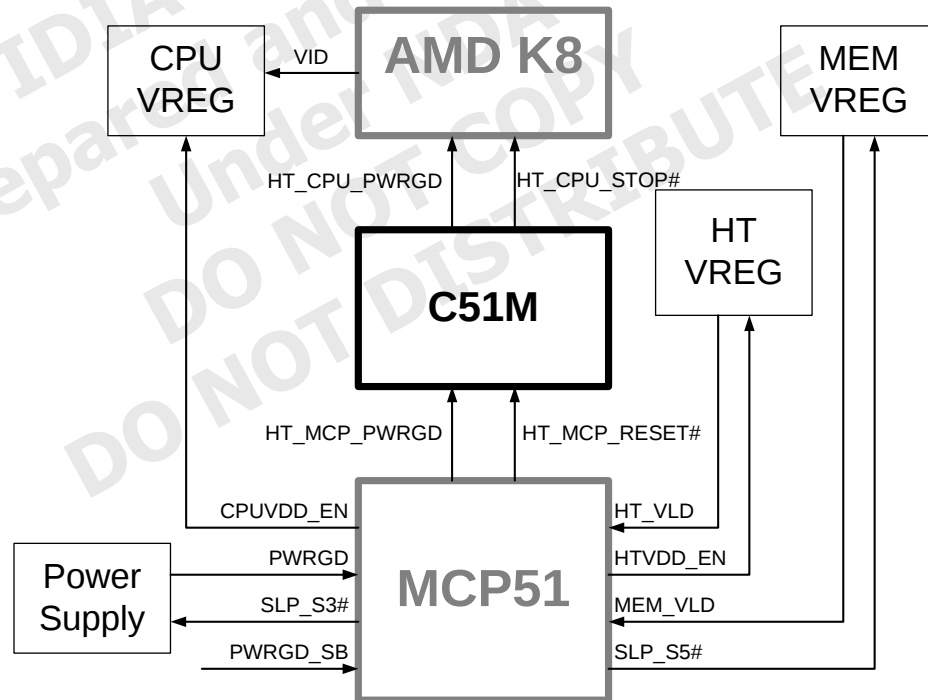


Figure 3. C51M Power Sequencing

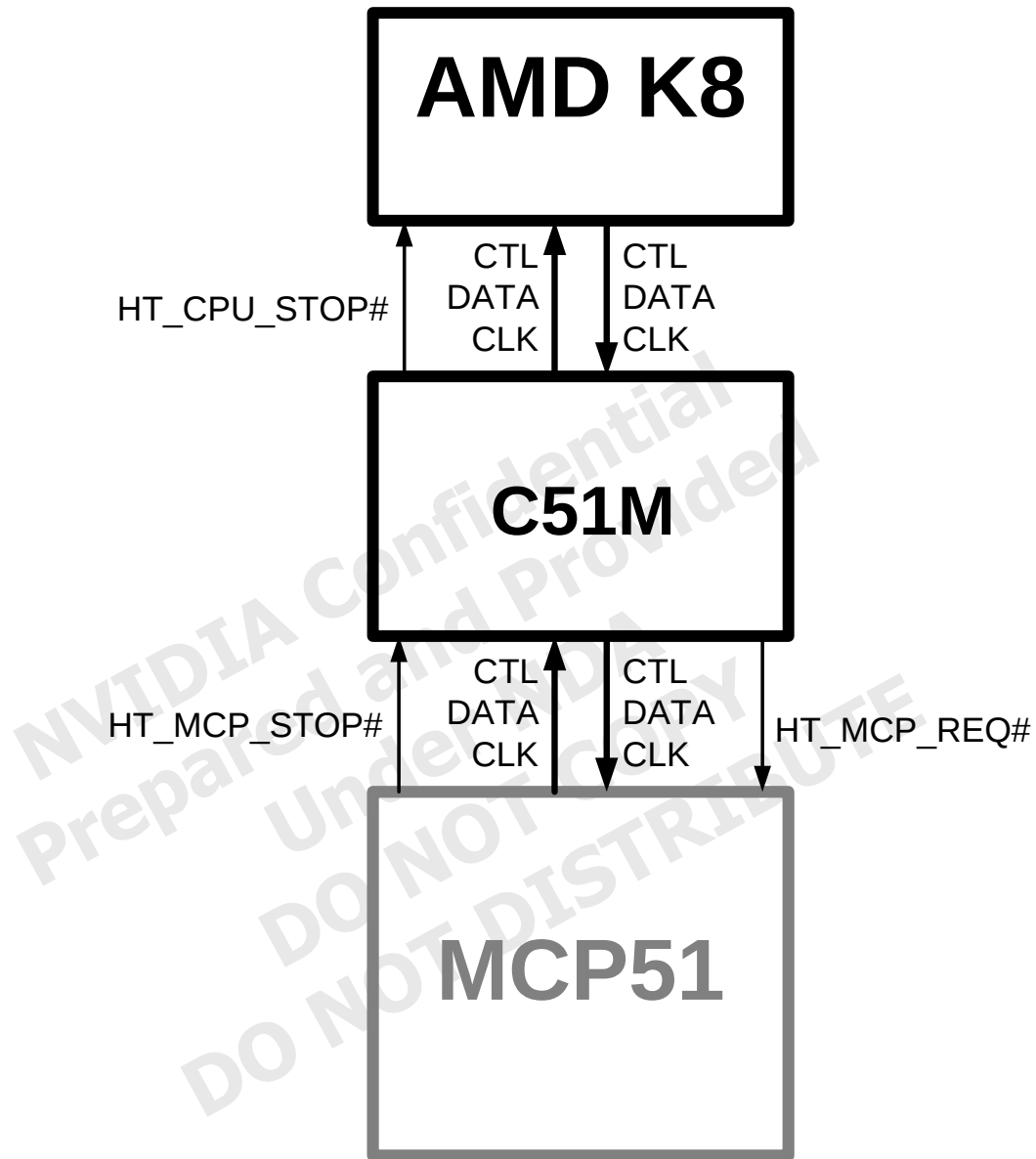
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Figure 4. HyperTransport Link Sequencing

Chapter 5. Pin States

Signal Connections

Table 20 lists the signal connections and Table 21 list the signal states.

Table 20. Signal Connections

Notes: I/O = Bidirectional OD = Open Drain I = Input O = Output OC = Open Collector			
Signal	I/O	Voltage Tolerance Rail	Voltage Drive Rail
HT_CPU_REQ#	I	+2.5V	+2.5V
HT_CPU_STOP#	OD	+2.5V	+2.5V
HT_CPU_RX_CLK[1:0]	DIFF IN	+1.2V_HT	
HT_CPU_RXCTL	DIFF IN	+1.2V_HT	
HT_CPU_RXD[15:0]	DIFF IN	+1.2V_HT	
HT_CPU_TX_CLK[1:0]	DIFF OUT	+1.2V_HT	+1.2V_HT
HT_CPU_TXCTL	DIFF OUT	+1.2V_HT	+1.2V_HT
HT_CPU_TXD[15:0]	DIFF OUT	+1.2V_HT	+1.2V_HT
HT_CPU_PWRGD	OD	+2.5V	+2.5V
HT_CPU_RESET#	OD	+2.5V	+2.5V
HT_MCP_REQ#	OD	+2.5V	+2.5V
HT_MCP_STOP#	I	+3.3V	
HT_MCP_RX_CLK[1:0]	DIFF IN	+1.2V_HTMCP	
HT_MCP_RX_CTL	DIFF IN	+1.2V_HTMCP	
HT_MCP_RXD[15:0]	DIFF IN	+1.2V_HTMCP	
HT_MCP_TX_CLK[1:0]	DIFF OUT	+1.2V_HTMCP	+1.2V_HTMCP
HT_MCP_TX_CTL	DIFF OUT	+1.2V_HTMCP	+1.2V_HTMCP
HT_MCP_TXD[15:0]	DIFF OUT	+1.2V_HTMCP	+1.2V_HTMCP
HT_MCP_PWRGD	I	+3.3V	
HT_MCP_RESET#	I	+3.3V	
PE0_PRSENT#	I	+3.3V	
PE0_REFCLK	DIFF OUT		+1.2V
PE0_RX[15:0]	DIFF IN	+1.5V_PE_A	

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Notes: I/O = Bidirectional OD = Open Drain I = Input O = Output OC = Open Collector			
Signal	I/O	Voltage Tolerance Rail	Voltage Drive Rail
PE0_TX[15:0]	DIFF OUT	+1.5V_PE_A	+1.5V_PE_A
PE1_CLKREQ#	I	+3.3V	
PE1_PRSNT#	I	+3.3V	
PE1_REFCLK	DIFF OUT		+1.2V
PE1_RX	DIFF IN	+1.5V_PE_A	
PE1_TX	DIFF OUT	+1.5V_PE_A	+1.5V_PE_A
PE2_CLKREQ#	I	+3.3V	
PE2_PRSNT#	I	+3.3V	
PE2_REFCLK	DIFF OUT	+3.3V	+1.2V
PE2_RX	DIFF IN	+1.5V_PE_A	
PE2_TX	DIFF OUT	+1.5V_PE_A	+1.5V_PE_A
PE_REFCLKIN	DIFF IN	+1.5V_PE_A	
PE_RESET#	O	+3.3V	+3.3V
IFPA_TXC	DIFF OUT	+2.5V/+3.0V	LVDS/TMDS Clock
IFPA_TXD[3:0]	DIFF OUT	+2.5V/+3.0V	LVDS/TMDS Data
IFPB_TXC	DIFF OUT	+2.5V/+3.0V	LVDS/TMDS Clock
IFPB_TXD[7:4]	DIFF OUT	+2.5V/+3.0V	LVDS/TMDS Data
DAC_RED	O	+3.3V	+3.3V
DAC_GREEN		+3.3V	+3.3V
DAC_BLUE		+3.3V	+3.3V
DAC_HSYNC	I/O	+3.3V	+3.3V
DAC_VSYNC	I/O	+3.3V	+3.3V
XTAL_IN	I/O	+2.5V	+2.5V
XTAL_OUT		+2.5V	+2.5V
CLKIN_25MHZ	I	+3.3V	
CLKIN_200MHZ	DIFF IN	+3.3V	
CLKOUT_PRI_200MHZ	DIFF OUT	+2.5V	+2.5V
CLKOUT_SEC_200MHZ	DIFF OUT	+2.5V	+2.5V
SCLKIN_MCLKOUT_200MHZ	DIFF I/O	+2.5V	+2.5V

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Signal States

Table 21. Signal States

Notes: Z = Tri-state I/O = Bidirectional I = Input O = Output OC = Open Collector OD = Open Drain U = Unpowered L = Low H=High					
Signal	During Reset	After RST (SO)	S1 (POS)	S3 (STR)	S4/S5 (SOFF)
HT_CPU_REQ#	I	I	I	U	U
HT_CPU_STOP#	O	O	L	U	U
HT_CPU_RX_CLK[1:0]	I	I	I	U	U
HT_CPU_RXCTL	I	I	I	U	U
HT_CPU_RXD[15:0]	I	I	I	U	U
HT_CPU_TX_CLK[1:0]	O	O	O	U	U
HT_CPU_TXCTL	Z	O	O	U	U
HT_CPU_TXD[15:0]	Z	O	O	U	U
HT_CPU_PWRGD	L/H	O	O	U	U
HT_CPU_RESET#	L	H	H	U	U
HT_MCP_REQ#	H	O	O	U	U
HT_MCP_STOP#	De-asserted at least 1 uS before HT_RESET	O	O	U	U
HT_MCP_RX_CLK[1:0]	O	O	O	U	U
HT_MCP_RX_CTL	O	O	O	U	U
HT_MCP_RXD[15:0]	O	O	O	U	U
HT_MCP_TX_CLK[1:0]	O	O	O	U	U
HT_MCP_TX_CTL	O	O	O	U	U
HT_MCP_TXD[15:0]	O	O	O	U	U
HT_MCP_PWRGD	I	I	I	U	U
HT_MCP_RESET#	I	I	I	U	U
PE0_PRSNT#	I	I	I	U	U
PE0_REFCLK	O	O	O	U	U
PE0_RX[15:0]	I	I	I	U	U
PE0_TX[15:0]	Z	O	O	U	U
PE1_CLKREQ#	I	I	I	U	U
PE1_PRSNT#	I	I	I	U	U
PE1_REFCLK	O	O	O	U	U
PE1_RX	I	I	I	U	U
PE1_TX	Z	O	O	U	U
PE2_CLKREQ#	I	I	I	U	U
PE2_PRSNT#	I	I	I	U	U
PE2_REFCLK	O	O	O	U	U

PROPRIETARY INFORMATION

Notes: Z = Tri-state I/O = Bidirectional I = Input O = Output OC = Open Collector OD = Open Drain U = Unpowered L = Low H=High					
Signal	During Reset	After RST (SO)	S1 (POS)	S3 (STR)	S4/S5 (SOFF)
PE2_RX	I	I	I	U	U
PE2_TX	Z	O	O	U	U
PE_REFCLKIN	I	I	I	U	U
PE_RESET#	L	O	O	U	U
IFPA_TXC	O	O	O	U	U
IFPA_TXD[3:0]	O	O	O	U	U
IFPB_TXC	O	O	O	U	U
IFPB_TXD[7:4]	O	O	O	U	U
DAC_RED	O	O	O	U	U
DAC_GREEN	O	O	O	U	U
DAC_BLUE	O	O	O	U	U
DAC_HSYNC	O	O	O	U	U
DAC_VSYNC	O	O	O	U	U
XTAL_IN	Z	Z	Z	U	U
XTAL_OUT	O	O	O	U	U
CLKIN_25MHZ	I	I	I	U	U
CLKIN_200MHZ	I	I	I	U	U
CLKOUT_PRI_200MHZ	O	O	O	U	U
CLKOUT_SEC_200MHZ	O	O	O	U	U
SCLKIN_MCLKOUT_200MHZ	Z	I/O	I/O	U	U

Chapter 6. Mechanical Specifications

The C51M is a 25×25 package with 468 balls at a 1mm ball pitch. Table 22 lists the package dimensions and Figure 9 shows the package drawings.

Table 22. PBGA Package Dimensions

Ref	Dimensions in Millimeter			Dimensions in Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.25	2.50	2.65	0.089	0.098	0.104
A1	0.43	0.52	0.60	0.017	0.020	0.024
A2	0.82	0.87	0.95	0.032	0.034	0.037
A5	0.46	0.53	0.58	0.018	0.021	0.023
D/E	24.30	24.50	24.70	0.857	0.985	0.972
D1/E1	23.00 BASIC			0.906 BASIC		
WxL	3.1 BASIC			0.12 BASIC		
WxR	3.5 BASIC			0.14 BASIC		
WyT	3.1 BASIC			0.12 BASIC		
WyB	4.6 BASIC			0.18 BASIC		
e	1.00 BASIC			0.039 BASIC		
b	0.51	0.60	0.74	0.020	0.024	0.029
aaa	0.20			0.006		
ccc	0.35			0.014		
ddd	0.20			0.006		
eee	0.30			0.012		
fff	0.10			0.004		
Total Number of Balls: 468						
Package Size: 25 mm × 25 mm						

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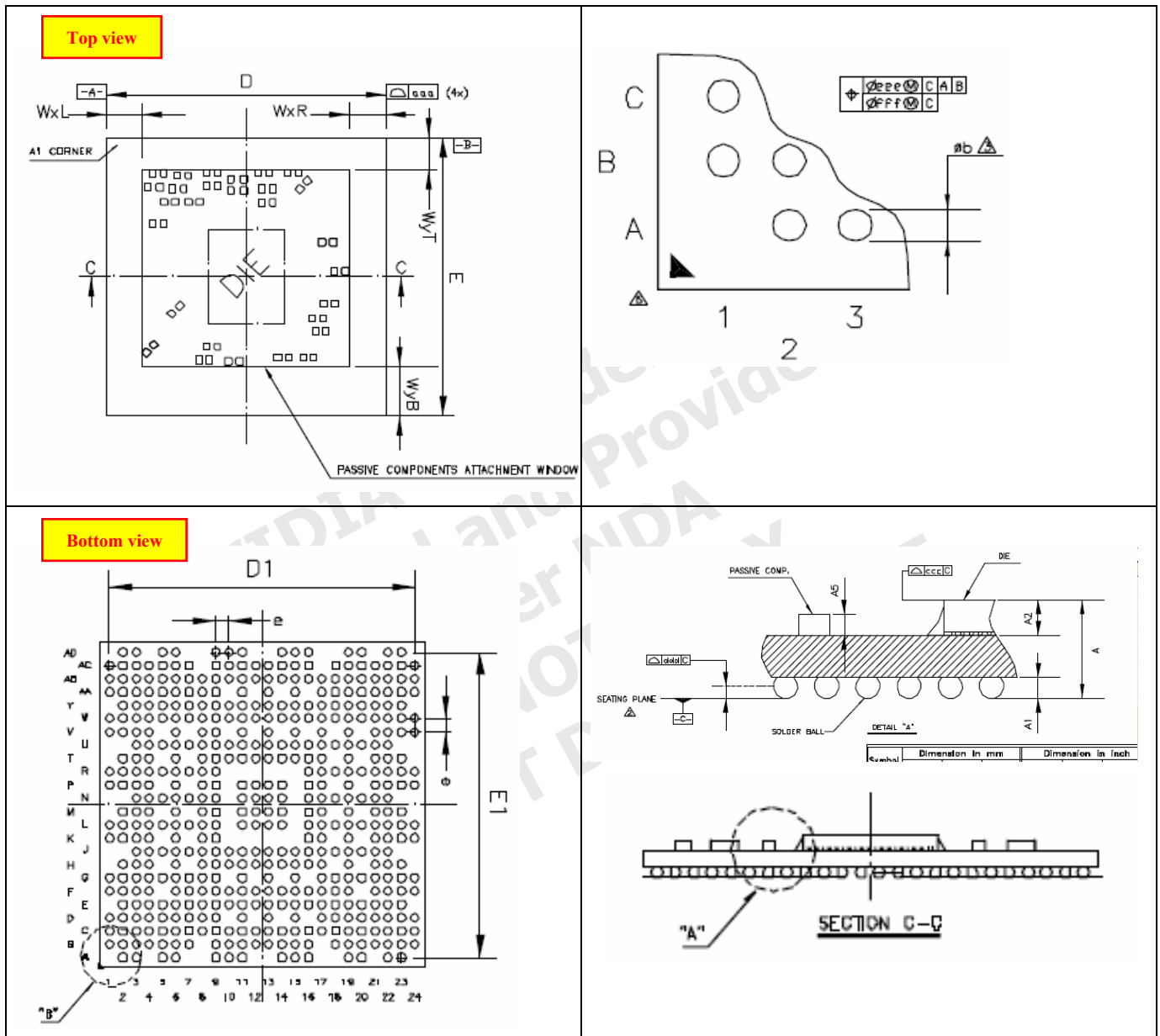


Figure 5. PBGA Package Drawing

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1. Controlling dimension: Millimeter
2. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.
3. Dimension b is measured at the maximum solder ball diameter, parallel to primary datum C.
4. There must be a minimum clearance of 0.15 mm (0.060 in.) between the edge of the solder ball and the body edge.
5. Die size approximately 6.7 x 8.3 mm (0.26 x 0.33 in.)
6. Die pattern of pin 1 fiducial is for reference only.
7. All passive locations shown. Some or all locations may not be populated.
8. Drawing *not* to scale.

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Chapter 7. AC/DC Specifications

Absolute Ratings

The NVIDIA C51M should not be subjected to conditions exceeding the absolute maximum ratings listed in Table 23. Exceeding the conditions listed can damage the functionality and affect the long-term reliability of the part.

Table 23. Absolute Ratings

Parameter	Min	Max
Case temperature under bias	0 °C	110 °C
Storage temperature	-50 °C	150 °C
Voltage on any 1.2 V pin with respect to ground	-0.5 V	1.3 V
Voltage on any 2.5 V pin with respect to ground	-0.5 V	2.7 V
Voltage on any 3.3 V pin with respect to ground	-0.5 V	3.6 V
1.2 V supply	-0.5 V	1.3 V
2.5V supply	-0.5 V	2.7 V
3.3 V supply	-0.5 V	3.6 V

Table 24. Maximum Power Dissipation

Power Dissipation	Maximum
C51M	7 W to 10 W

Note: These maximum power numbers are estimates.

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Thermal Operations

The thermal operating temperature range is given in Table 25.

Table 25. Thermal Operating Temperature

Characteristic	Range
Thermal operating temperature (T_{CASE})	0°C to TBD

DC Voltage Characteristics

Table 26 lists the voltage characteristics for NVIDIA C51M.

Table 26. Voltage Characteristics

Signal	Min	Max	Range
+1.2V_CORE	1.14 V	1.26 V	± 0.06 V
+1.2V_HT	1.14 V	1.26 V	± 0.06 V
+1.2V_HTMCP	1.14 V	1.26 V	± 0.06 V
+1.2V_PEA	1.14 V	1.26 V	± 0.06 V
+1.2V_PED	1.14 V	1.26 V	± 0.06 V
+1.2V_PLL	1.14 V	1.26 V	± 0.06 V
+1.2V_PLLCORE	1.14 V	1.26 V	± 0.06 V
+1.2V_PLLHTMCP	1.14 V	1.26 V	± 0.06 V
+1.2V_PLLIFP	1.14 V	1.26 V	± 0.06 V
+2.5V_CORE	2.3 V	2.7 V	± 0.20 V
+2.5V_IFPA	2.3 V/+3.0V	2.7 V/+3.3V	± 0.20 V/ ± 0.3 V
+2.5V_IFPB	2.3 V/+3.0V	2.7 V/+3.3V	± 0.20 V/ ± 0.3 V
+2.5V_PLLCORE	2.3 V	2.7 V	± 0.20 V
+2.5V_PLGPU	2.3 V	2.7 V	± 0.20 V
+2.5V_PLLHTCPU	2.3 V	2.7 V	± 0.20 V
+2.5V_PLLIFP	2.3 V	2.7 V	± 0.20 V
+3.3V	3.0 V	3.3 V	± 0.3 V
+3.3V_DAC	3.0 V	3.3 V	± 0.3 V

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AC Characteristics

This section contains the following AC specifications:

- Input clock characteristics
- Output clock characteristics
- Interface characteristics
 - HyperTransport Interface
 - PCI Express Interface

Input Clock Characteristics

Table 27 provides the input clock characteristics.

Table 27. AC Input Clock Characteristics

Clock	Characteristic	Min	Typical	Max	Comments
27MHz Crystal (XTAL_IN/XTAL_OUT)	Clock frequency		27 MHz		
	Clock period		37 ns		
	Clock high time	17 ns		20 ns	55/45 duty cycle
	Clock low time	17 ns		20 ns	55/45 duty cycle
	Clock rise time	1 ns		4 ns	
	Clock fall time	1 ns		4 ns	
CLKIN_25MHZ	Clock frequency		25 MHz		
	Clock period		40 ns		
	Clock high time	18 ns		22 ns	55/45 duty cycle
	Clock low time	18 ns		22 ns	55/45 duty cycle
	Clock rise time	1 ns		4 ns	
	Clock fall time	1 ns		4 ns	
CLKIN_200MHZ	Clock frequency		200 MHz		
	Clock period		5 ns		
	Clock high time	2.25 ns		2.75 ns	55/45 duty cycle
	Clock low time	2.25 ns		2.75 ns	55/45 duty cycle
PE_REFCLKIN	Clock frequency		100 MHz		
	Clock period		10 ns		
	Clock high time	4.5 ns		5.5 ns	55/45 duty cycle
	Clock low time	4.5 ns		5.5 ns	55/45 duty cycle
SCLKIN_MCLKOUT_200MHZ	Clock frequency		200 MHz		
	Clock period		5 ns		
	Clock high time	2.25 ns		2.75 ns	55/45 duty cycle
	Clock low time	2.25 ns		2.75 ns	55/45 duty cycle

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Output Clock Characteristics

Table 28 lists the AC output clock characteristics and Figure 8 shows clock timing.

Table 28. AC Output Clock Characteristics

Clock	Characteristic	Min	Typical	Max	Comments
CLKOUT_PRI_200MHZ CLKOUT_SEC_200MHZ	Clock frequency		200 MHz		
	Clock period		5 ns		
	Clock high time	2.25 ns		2.75 ns	55/45 duty cycle
	Clock low time	2.25 ns		2.75 ns	55/45 duty cycle
	Clock rise time	TBD		TBD	
	Clock fall time	TBD		TBD	
PE[2:0]_REFCLK	Clock frequency		100 MHz		
	Clock period		10 ns		
	Clock high time	4.5 ns		5.5 ns	55/45 duty cycle
	Clock low time	4.5 ns		5.5 ns	55/45 duty cycle
SCLKIN_MCLKOUT_ 200 MHZ	Clock frequency		200 MHz		
	Clock period		5 ns		
	Clock high time	2.25 ns		2.75 ns	55/45 duty cycle
	Clock low time	2.25 ns		2.75 ns	55/45 duty cycle
	Clock rise time	TBD		TBD	
	Clock fall time	TBD		TBD	

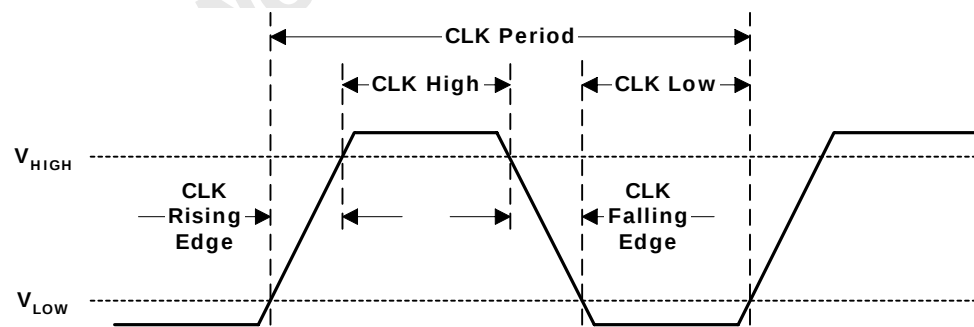


Figure 6. Clock Timing Diagram

PROPRIETARY INFORMATION

Interface Characteristics

The AC interface characteristics are explained in the following tables and diagrams.

HyperTransport Interface

The HyperTransport interface is compliant with the *HyperTransport I/O Link Specification* published by the HyperTransport Technology Consortium. Refer to that document for full details of the interface timing.

NVIDIA C51M meets the timing requirements for transmit and receive up to a link speed of 3200 MT/s.

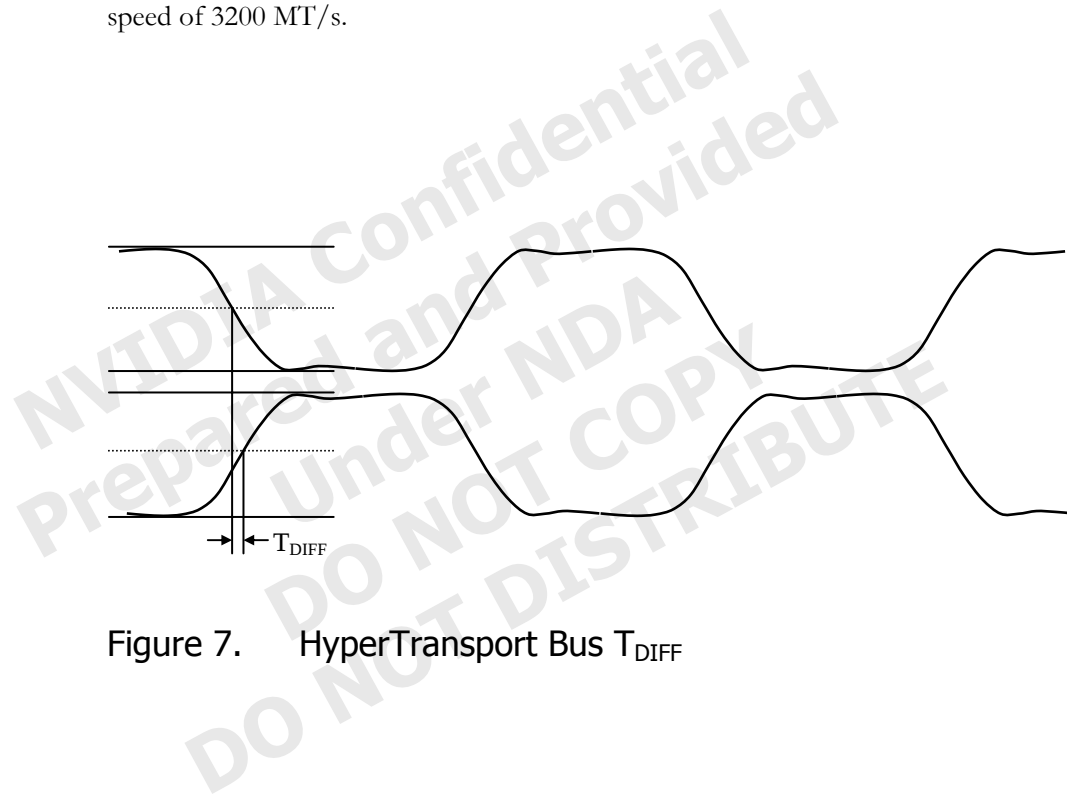
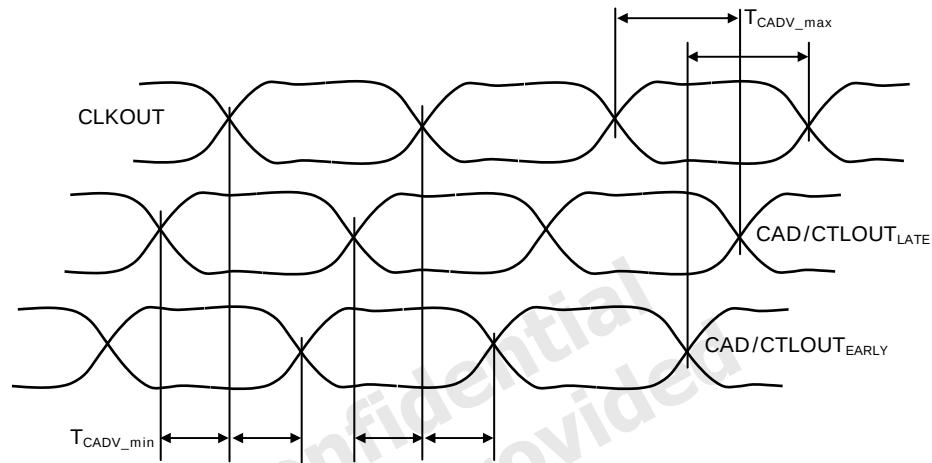
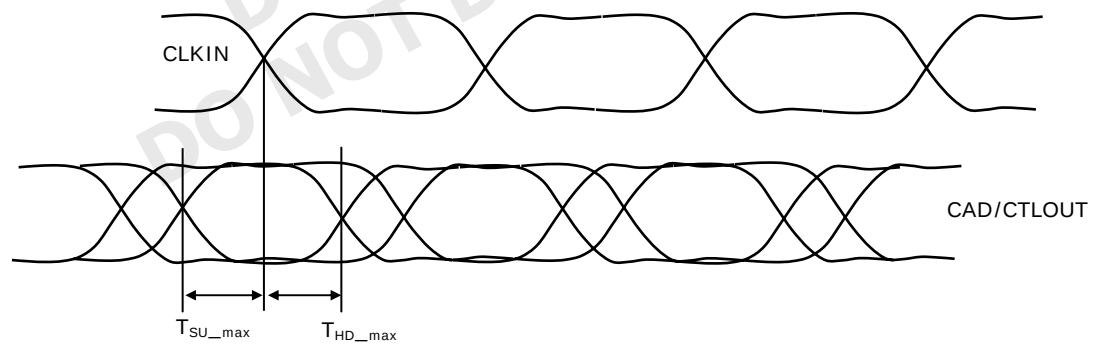


Figure 7. HyperTransport Bus T_{DIFF}

PROPRIETARY INFORMATIONFigure 8. HyperTransport Bus T_{CAD}Figure 9. HyperTransport Bus T_{SU} and T_{HD}

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Table 29. HyperTransport Bus

Symbol	Characteristic	Link Speed	Min	Max	Comments
T_{ODIFF}	Output differential skew	800 MT/s		70 ps	
		1200 MT/s		70 ps	
		1600 MT/s		70 ps	
		2000 MT/s		60 ps	
		2400 MT/s		60 ps	
		3200 MT/s		60 ps	
T_{IDIFF}	Input differential skew	800 MT/s		90 ps	
		1200 MT/s		90 ps	
		1600 MT/s		90 ps	
		2000 MT/s		65 ps	
		2400 MT/s		65 ps	
		3200 MT/s		65 ps	
T_{CADV}	Transmitter output CAD/CTLOUT valid relative to CLKOUT	800 MT/s	695 ps	1805 ps	
		1200 MT/s	467 ps	1200 ps	
		1600 MT/s	345 ps	905 ps	
		2000 MT/s	280 ps	720 ps	
		2400 MT/s	213 ps	620 ps	
		3200 MT/s	166 ps	459 ps	
T_{CADVRS}	Receiver input CADIN valid time to CLKIN	800 MT/s	460 ps		
		1200 MT/s	312 ps		
		1600 MT/s	225 ps		
		2000 MT/s	194 ps		
		2400 MT/s	166 ps		
		3200 MT/s	116 ps		
T_{CADVRH}	Receiver input CADIN valid time from CLKIN	800 MT/s	460 ps		
		1200 MT/s	312 ps		
		1600 MT/s	225 ps		
		2000 MT/s	194 ps		
		2400 MT/s	166 ps		
		3200 MT/s	116 ps		
T_{SU}	Receiver input setup time	800 MT/s		250 ps	
		1200 MT/s		215 ps	
		1600 MT/s		175 ps	
		2000 MT/s		153 ps	
		2400 MT/s		138 ps	
		3200 MT/s		110 ps	
T_{HD}	Receiver input hold time	800 MT/s		250 ps	
		1200 MT/s		215 ps	
		1600 MT/s		175 ps	
		2000 MT/s		153 ps	
		2400 MT/s		138 ps	
		3200 MT/s		110 ps	

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The PCI Express interface is compliant with the *PCI Express Base Specification* published by the PCI SIG. Refer to that document for full details of the interface timing.

The NVIDIA C51M meets the timing requirements for transmit and receive at a link speed of 2.5 Gb/s.

Table 30. Differential Transmitter (TX) Output Specifications

Symbol	Parameter	Min	Nom	Max	Units	Comments
UI	Unit interval	399.88	400	400.12	ps	Each UI is 400ps +/-300ppm. UI does not account for SSC (spread spectrum clock) dictated variations. See Note 1.
$V_{TX-DIFFP-P}$	Differential peak-to-peak output voltage	0.800		1.2	V	$V_{TX-DIFFP-P} = 2 * V_{TX-D+} - V_{TX-D-} $. See Note 2.
$V_{TX-DE-RATIO}$	De-emphasized differential output voltage (ratio)	-3.0	-3.5	-4.0	dB	This is the ratio of the $V_{TX-DIFFP-P}$ of the second and following bits after a transition divided by the $V_{TX-DIFFP-P}$ of the first bit after a transition. See Note 2.
V_{TX-EYE}	Minimum TX eye width	0.70			UI	The maximum transmitter jitter can be derived as $T_{TX-MAX} JITTER = 1 - T_{TX-EYE} = 0.3$ UI. See Notes 2 and 3.
$V_{TX-EYE-MEDIAN-TO-MAX-JITTER}$	Maximum time between jitter median and maximum deviation from the median			0.15	UI	Jitter is defined as the measurement variation of the crossing points ($V_{TX-DIFFP-P} = 0$ V) in relation to an appropriate average TX UI. See Notes 2 and 3.
$V_{TX-RISE}$, $V_{TX-FALL}$	D+/D- TX output rise/fall time	0.125			UI	See Notes 2 and 5.
$V_{TX-CM-ACP}$	AC peak common mode output voltage			20	mV	$V_{TX-CM-ACP} = V_{TX-D+} + V_{TX-D-} /2 - V_{TX-CM-DC}$ $V_{TX-CM-DC} = DC(aveg)$ of $ V_{TX-D+} + V_{TX-D-} /2$ during L0. See Note 2.

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Symbol	Parameter	Min	Nom	Max	Units	Comments
$V_{TX-CM-DC-ACIVE-IDLE-DELTA}$	Absolute delta of DC common mode voltage during L0 and electrical idle	0		100	mV	$ V_{TX-CM-DC} \text{ [during L0]} - V_{TX-CM-IDLE-DC} \text{ [during Electrical Idle]} \leq 100 \text{ mV}$ $V_{TX-CM-DC} = DC(\text{avg}) \text{ of } V_{TX-D+} + V_{TX-D-} /2 \text{ [L0]}$ $V_{TX-CM-IDLE-DC} = DC(\text{avg}) \text{ of } V_{TX-D+} + V_{TX-D-} /2 \text{ [Electrical Idle]}.$ See Note 2.
$V_{TX-CM-DC-LINE-DELTA}$	Absolute delta of DC common mode voltage between D+ and D-	0		25	mV	$ V_{TX-CM-DC-D+} \text{ [during L0]} - V_{TX-CM-IDLE-DC-D-} \text{ [during L0]} \leq 25 \text{ mV}$ $V_{TX-CM-DC-D+} = DC(\text{avg}) \text{ of } V_{TX-D+} \text{ [during L0]}$ $V_{TX-CM-DC-D-} = DC(\text{avg}) \text{ of } V_{TX-D-} \text{ [during L0]}.$ See Note 2.
$V_{TX-IDLE-DIFFp}$	Electrical idle differential peak output voltage	0		20	mV	$V_{TX-IDLE-DIFFp} = V_{TX-IDLE-D+} - V_{TX-IDLE-D-} \leq 20 \text{ mV}$ See Note 2.
$V_{TX-RCV-DETECT}$	The amount of voltage change allowed during receiver detection			600	mV	The total amount of voltage change that a transmitter can apply to sense whether a low impedance receiver is present. See Figure 8.
$V_{TX-IDLE-MIN}$	Minimum time spec in electrical idle	50			UI	Minimum time a transmitter must be electrical idle.
$V_{TX-IDLE-SET-TO-IDLE}$	Maximum time to transition to a valid electrical idle after sending an electrical idle ordered set			20	UI	After sending an electrical idle ordered-set, the transmitter must meet all electrical idle specifications within this time.
$V_{TX-IDLE-RCVDETECT-MAX}$	Maximum time spent in electrical idle before initiating a receiver detect sequence			100	ms	Maximum time spent in electrical idle before initiating a receiver detect sequence. See Figure 8.
$RL_{TX-DIFF}$	Differential return loss	12			dB	Measured over 50 MHz to 1.25 GHz. See Note 4.
RL_{TX-CM}	Common mode return loss	6			dB	Measured over 50 MHz to 1.25 GHz. See Note 4.
$Z_{TX-DIFF-DC}$	DC differential TX impedance	80	100	120	Ω	TX DC differential mode low impedance.
$Z_{TX-COM-High-IMP-DC}$	Transmitter common mode high impedance state (DC)	5		20	K Ω	TX DC high impedance.
$L_{TX-SKEW}$	Lane-to-lane skew			500	ps	Between any two lanes within a single transmitter.

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Symbol	Parameter	Min	Nom	Max	Units	Comments
C _{TX}	AC coupling capacitor	75		200	pF	All transmitters shall be AC coupled. The AC coupling is required either within the media or within the transmitting component itself.

Notes:

1. No test load is necessarily associated with this value.
2. Specified at the measurement point into a timing and voltage compliance test load as shown in Figure 4-31 of the PCI Express Base Specification Revision 1.0 and measured over any 250 consecutive TX UIs. (Also refer to the Transmitter Compliance Eye Diagram shown in Figure 4-30 of the PCI Express Base Specification Revision 1.0.)
3. A TTX-EYE = 0.70 UI provides for a total sum of deterministic and random jitter budget of TTX-JITTER-MAX = 0.30 UI for the transmitter collected over any 250 consecutive TX UIs. The TTX-EYE-MEDIAN-TO-MAX-JITTER specification ensures a jitter distribution in which the median and the maximum deviation from the median is less than half of the total TX jitter budget collected over any 250 consecutive TX UIs. It should be noted that the median is not the same as the mean. The jitter median describes the point in time where the number of jitter points on either side is approximately equal as opposed to the average time value.
4. The transmitter output impedance shall result in a differential return loss greater than or equal to 12 dB and a common mode return loss greater than or equal to 6 dB over a frequency range of 50 MHz to 1.25 GHz. This input impedance requirement applies to all valid input levels. The reference impedance for return loss measurements is 50 ohms to ground for both the D+ and D- line (i.e., as measured by a Vector Network Analyzer with 50 ohm probes – see Figure 4-31 of the PCI Express Base Specification Revision 1.0). Note that the series capacitor C_{TX} is optional for the return loss measurement.
5. Measured between 20%-80% at transmitter package pins into a test load as shown in Figure 4-31 for both VTX-D+ and VTX-D-.

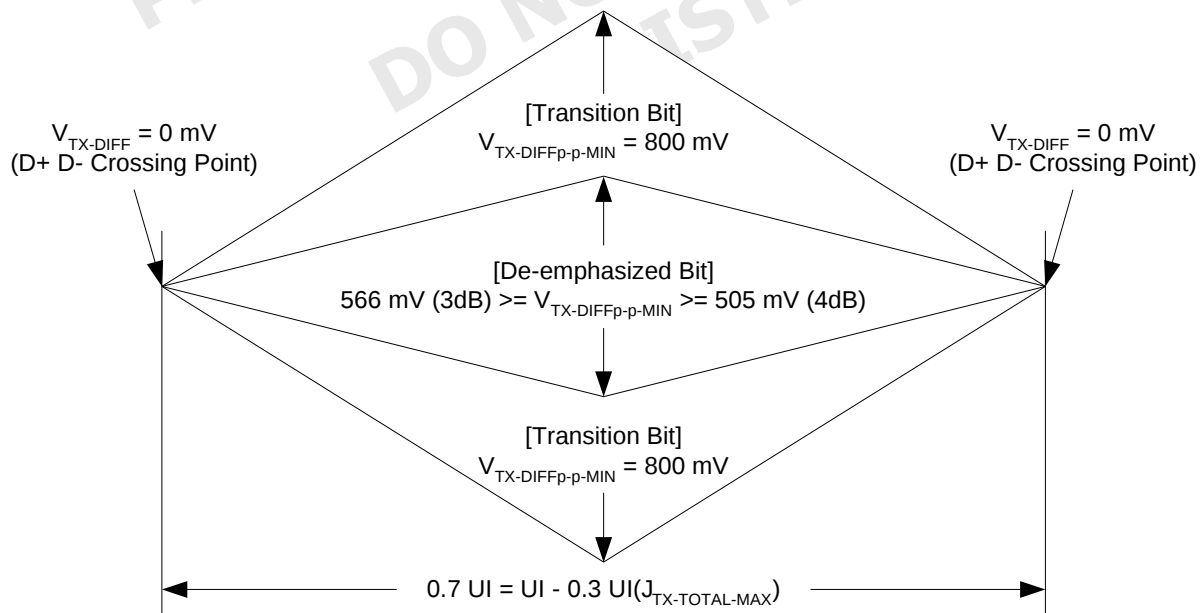


Figure 10. Minimum TX Eye Timing and Voltage Compliance

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Table 31. Differential Receiver (RX) Output Specifications

Symbol	Parameter	Min	Nom	Max	Units	Comments
UI	Unit interval	399.88	400	400.12	ps	Each UI is 400ps +/-300 ppm. UI does not account for SSC dictated variations. See Note 6.
$V_{RX-DIFFp-p}$	Differential input peak-to-peak voltage	0.175		1.2	V	$V_{RX-DIFFp-p} = 2 * V_{RX-D+} - V_{RX-D-} $. See Note 7.
V_{RX-EYE}	Minimum RX eye width	0.40			UI	The maximum interconnect media and transmitter jitter can be tolerated by the receiver can be derived as $T_{RX-MAX JITTER} = 1 - T_{RX-EYE} = 0.6$ UI. See Notes 7 and 8.
$V_{TX-EYE-MEDIAN-TO-MAX-JITTER}$	Maximum time between the jitter median and maximum deviation from the median			0.3	UI	Jitter is defined as the measurement variation of the crossing points ($V_{RX-DIFFp-p} = 0$ V) in relation to an appropriate average TX UI. See Notes 7 and 8.
$V_{RX-CM-ACp}$	AC peak common mode input voltage			150	mV	$V_{RX-CM-ACp} = V_{RX-D+} + V_{RX-D-} /2 - V_{RX-CM-DC}$ $V_{RX-CM-DC} = DC(avg)$ of $ V_{RX-D+} + V_{RX-D-} /2$ during L0. See Note 7.
$RL_{RX-DIFF}$	Differential return loss	15			dB	Measured over 50 MHz to 1.25 GHz. See Note 9.
R_{RX-CM}	Common mode return loss	6			dB	Measured over 50 MHz to 1.25 GHz. See Note 9.
$Z_{RX-DIFF-DC}$	DC differential RX impedance	80	100	120	Ω	RX DC differential mode low impedance. See Note 10.
$Z_{RX-COM-DC}$	DC input common mode input impedance	40	50	60	Ω	RX DC common mode impedance 50 ohms +/-20% tolerance. See Note 7 and 10.
$Z_{RX-COM-INITIAL-DC}$	Initial DC input common mode input impedance	5	50	60	Ω	RX DC common mode impedance allowed when the receiver terminations are first powered on. See Note 11
$Z_{RX-COM-HIGH-IMP-DC}$	Powered down DC input common mode input impedance	200			K Ω	RX DC common mode impedance when the receiver terminations are not powered (i.e., no power). See Note 12
$V_{RX-IDLE-DET-DIFFp-p}$	Electrical idle threshold	65		175	mV	$V_{RX-IDLE-DET-DIFFp-p} = 2 * V_{RX-D+} - V_{RX-D-} $ Measured at the package pins of the receiver.

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Symbol	Parameter	Min	Nom	Max	Units	Comments
$T_{RX-IDLE-DET-OFF-ENTERTIME}$	Unexpected electrical idle enter detect threshold integration time			10	ms	An unexpected electrical idle ($V_{RX-DIFFP-P} < V_{RX-IDLE-DET-DIFFP-P}$) must be recognized no longer than $V_{RX-IDLE-DET-OFF-ENTERTIME}$ to signal an unexpected idle condition.
$L_{TX-SKEW}$	Lane-to-lane skew			20	ns	Across all lanes on a port. This includes variation in the length of a skip ordered-set (e.g., COM and 1 to 5 SKP symbols) at the RX as well as any delay differences arising from the interconnect itself.

Notes:

6. No test load is necessarily associated with this value.
7. Specified at the measurement point and measured over any 250 consecutive UIs. The test load in Figure 4-31 of the PCI Express Base Specification Revision 1.0 should be used as the RX device when taking measurements (Also refer to the Receiver Compliance Eye Diagram shown in Figure 4-32 of the PCI Express Base Specification Revision 1.0). If the clocks to the RX and TX are not derived from the same clock chip the TX UI must be used as a reference for the eye diagram.
8. A TRX-EYE = 0.40 UI provides for a total sum of 0.60 UI deterministic and random jitter budget of the TX and interconnect collected any 250 consecutive UIs. The TRX-EYE-MEDIAN-TO-MAX-JITTER specification ensures a jitter distribution in which the median and the maximum deviation from the median is less than half of the total 0.60 UI jitter budget collected over any 250 consecutive TX UIs. It should be noted that the median is not the same as the mean. The jitter median describes the point in time where the number of jitter points on either side is approximately equal as opposed to the average time value. If the clocks to the RX and TX are not derived from the same clock chip, the appropriate average TX UI must be used as the reference for the eye diagram.
9. The receiver input impedance shall result in a differential return loss greater than or equal to 15 dB and a common mode return loss greater than or equal to 6 dB over a frequency range of 50 MHz to 1.25 GHz. This input impedance requirement applies to all valid input levels. The reference impedance for return loss measurements is 50 ohms to ground for both the D+ and D- line (i.e., as measured by a Vector Network Analyzer with 50 ohm probes – see Figure 4-31 of the PCI Express Base Specification Revision 1.0). Note that the series capacitor CTX is optional for the return loss measurement.
10. Impedance during all operating conditions.
11. The RX DC common mode impedance that must be present when the receiver terminations are first enabled to ensure that the receiver-detect occurs properly. Compensation of this impedance can start immediately and the (ZRX-COM-DC) RX DC common mode impedance must be within the specified range by the time Detect is entered.
12. The RX DC common mode impedance that exists when the receiver terminations are disabled or when no power is present. This helps ensure that the receiver-detect circuit does not falsely assume a receiver is powered on when it is not.

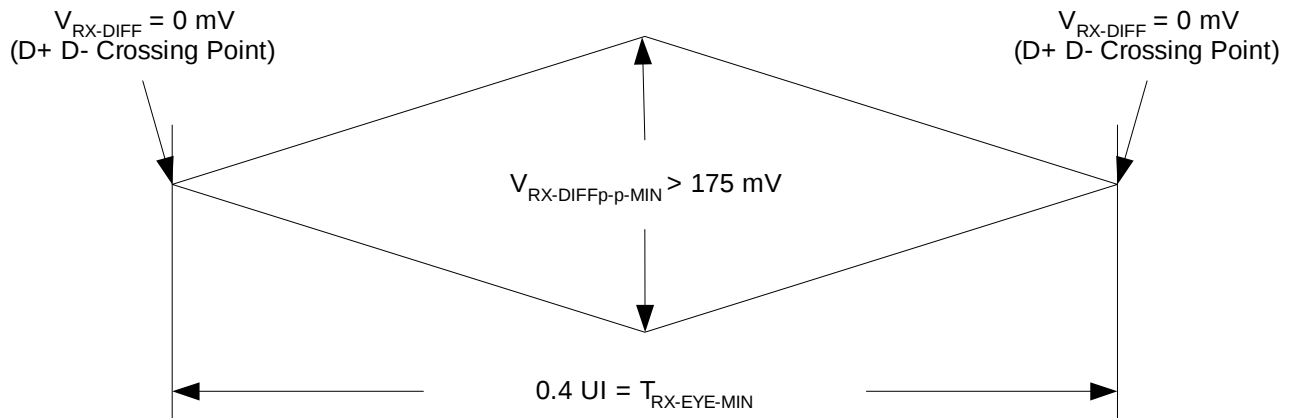
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Figure 11. Minimum RX Eye Timing and Voltage Compliance

Industry Standards

The following industry standard documents are referenced in this document. You should reference these as well as this document.

- *HyperTransport I/O Link Specification*
Revision 1.03, HyperTransport Technology Consortium
- *ELA/JEDEC Standard ELA/JESD8-5*
October 1995

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Appendix A. Ball Listings

Table 32 provides the ball listing by package ball and Table 33 provides the ball listing by the signal name.

Table 32. Ball Listing by Package Ball

Ball	Signal Name
A2	+1.2V_PLL
A3	+1.2V_PEA
A5	DAC_RED
A6	DAC_BLUE
A9	+3.3V_DAC
A10	IFPB_TXC_P
A11	IFPB_TXD4_N
A14	IFPA_TXD2_P
A15	IFPA_TXD0_P
A16	IFPAB_VPROBE
A19	JTAG_TRST#
A20	SCLKIN_MCLKOUT_200MHZ_P
A22	CLKOUT_SEC_200MHZ_P
A23	GND
B1	GND
B2	+1.2V_PLL
B3	+1.2V_PEA
B4	+1.2V_PED
B5	+1.2V_CORE
B6	DAC_GREEN
B7	DAC_HSYNC
B9	XTAL_OUT
B10	IFPB_TXC_N

Ball	Signal Name
B11	IFPB_TXD4_P
B12	IFPB_TXD7_P
B13	IFPA_TXC_N
B14	IFPA_TXD2_N
B15	IFPA_TXD0_N
B16	+2.5V_CORE
B18	JTAG_TMS
B19	JTAG_TDI
B20	SCLKIN_MCLKOUT_200MHZ_N
B21	CLKOUT_SEC_200MHZ_N
B22	CLKOUT_CTERM_GND
B23	CLKOUT_PRI_200MHZ_N
B24	CLKOUT_PRI_200MHZ_P
C1	GND
C2	+1.2V_PLL
C3	+1.2V_PLL
C4	+1.2V_PEA
C5	+1.2V_PED
C6	+1.2V_CORE
C7	DAC_VSYNC
C8	DAC_IDUMP
C9	XTAL_IN

Ball	Signal Name
C10	+3.3V
C11	GND
C12	IFPB_TXD7_N
C13	IFPB_TXD6_N
C14	IFPA_TXC_P
C15	IFPA_TXD1_N
C16	+2.5V_CORE
C17	TEST_MODE_EN
C18	JTAG_TCK
C19	JTAG_TDO
C20	GND
C21	+1.2V_HT
C22	GND
C23	HT_CPU_TXD0_P
C24	HT_CPU_TXD0_N
D1	PE0_PRSENT#
D2	PE_CTERM_GND
D3	PE1_CLKREQ#
D4	+1.2V_PLL
D5	+1.2V_PEA
D6	+1.2V_PED
D7	+1.2V_CORE
D8	DAC_RSET
D9	DAC_VREF
D11	GND

PROPRIETARY INFORMATION

Ball	Signal Name
D13	IFPB_TXD6_P
D15	IFPA_TXD1_P
D17	PKG_TEST
D18	+3.3V
D19	GND
D20	HT_CPU_RESET#
D21	HT_CPU_TXD8_P
D22	HT_CPU_TXD8_N
D23	HT_CPU_TXD1_P
D24	HT_CPU_TXD1_N
E2	PE1_PRSENT#
E3	PE2_PRSENT#
E4	PE2_CLKREQ#
E5	+1.2V_PLL
E6	+1.2V_PEA
E7	+1.2V_PED
E8	+1.2V_CORE
E9	+1.2V_CORE
E10	+1.2V_CORE
E11	NC
E12	GND
E13	IFPB_TXD5_P
E14	IFPA_TXD3_N
E15	GND
E16	+2.5V_PLLIFP
E17	NC
E18	GND
E19	HT_CPU_PWRGD
E20	HT_CPU_TXD9_N
E21	HT_CPU_TXD10_N
E22	HT_CPU_TXD2_P
E23	HT_CPU_TXD2_N
F1	PE_TSTCLK_P
F2	PE_TSTCLK_N
F3	PE_GND
F4	PE_GND
F6	+1.2V_PLL
F7	+1.2V_PEA
F8	+1.2V_PEA
F9	+1.2V_PEA
F10	+1.2V_CORE

Ball	Signal Name
F11	+1.2V_CORE
F12	NC
F13	IFPB_TXD5_N
F14	IFPA_TXD3_P
F15	IFPAB_RSET
F16	GND
F17	NC
F18	HT_CPU_REQ#
F19	HT_CPU_TXD9_P
F21	HT_CPU_TXD10_P
F22	GND
F23	HT_CPU_TXD3_P
F24	HT_CPU_TXD3_N
G1	PE_RESET#
G2	PE1_REFCLK_P
G3	PE1_REFCLK_N
G4	PE1_TX_P
G5	PE1_TX_N
G6	PE1_RX_P
G7	+1.2V_PLL
G8	+1.2V_PLL
G9	+1.2V_PLL
G11	+1.2V_CORE
G13	GND
G15	+2.5V_IFPA
G17	NC
G18	HT_CPU_STOP#
G19	HT_CPU_TXD11_N
G20	HT_CPU_TXD11_P
G21	HT_CPU_TX_CLK1_N
G22	HT_CPU_TX_CLK1_P
G23	HT_CPU_TX_CLK0_P
G24	HT_CPU_TX_CLK0_N
H2	PE2_REFCLK_P
H3	PE2_REFCLK_N
H4	PE2_TX_P
H6	PE1_RX_N
H8	PE_GND
H9	PE_GND
H10	+1.2V_PLL
H11	+1.2V_CORE

Ball	Signal Name
H12	+2.5V_PLLCORE
H13	+2.5V_PLGPU
H14	GND
H15	+2.5V_IFPB
H16	+1.2V_PLLIFP
H17	+1.2V_HT
H19	GND
H21	GND
H22	HT_CPU_TXD4_P
H23	HT_CPU_TXD4_N
J3	PE2_TX_N
J4	PE2_RX_P
J5	PE0_RX1_N
J6	PE0_RX1_P
J7	PE0_RX0_N
J8	PE0_RX0_P
J9	PE0_RX2_N
J10	+1.2V_PLL
J11	+1.2V_CORE
J12	+1.2V_CORE
J13	+1.2V_CORE
J14	+1.2V_CORE
J15	GND
J16	GND
J17	GND
J18	HT_CPU_TXD12_N
J19	HT_CPU_TXD12_P
J20	+1.2V_HT
J21	HT_CPU_TXD5_P
J22	HT_CPU_TXD5_N
K1	PE0_REFCLK_P
K2	PE0_REFCLK_N
K3	PE2_RX_N
K4	PE_GND
K6	PE_GND
K8	PE_GND
K9	PE0_RX2_P
K16	+1.2V_HT
K17	HT_CPU_TXD13_N
K19	HT_CPU_TXD14_N
K21	HT_CPU_TXD6_P

PROPRIETARY INFORMATION

Ball	Signal Name
K22	HT_CPU_TXD6_N
K23	HT_CPU_TXD7_P
K24	HT_CPU_TXD7_N
L1	PE0_TX0_P
L2	PE0_TX0_N
L3	PE0_TX1_P
L4	PE0_TX2_P
L5	PE0_RX3_N
L6	PE0_RX3_P
L7	PE0_RX4_P
L8	PE0_RX4_N
L9	PE_GND
L11	GND
L12	GND
L13	GND
L14	GND
L16	+2.5V_PLLHTCPU
L17	HT_CPU_TXD13_P
L18	HT_CPU_TXD15_P
L19	HT_CPU_TXD15_N
L20	HT_CPU_TXD14_P
L21	GND
L22	GND
L23	HT_CPU_TXCTL_P
L24	HT_CPU_TXCTL_N
M2	PE0_TX1_N
M3	PE0_TX2_N
M4	PE0_TX3_P
M6	PE_GND
M8	PE0_RX5_N
M9	PE0_RX5_P
M11	GND
M12	GND
M13	GND
M14	GND
M16	+1.2V_HT
M17	HT_CPU_RXD15_P
M19	GND
M21	+1.2V_HT
M22	HT_CPU_RXCTL_N
M23	HT_CPU_RXCTL_P

Ball	Signal Name
N3	PE0_TX3_N
N4	PE_GND
N5	PE0_RX7_N
N6	PE0_RX7_P
N7	PE0_RX6_N
N8	PE0_RX6_P
N9	PE_GND
N11	GND
N12	GND
N13	GND
N14	GND
N16	+1.2V_PLLHTCPU
N17	GND
N18	HT_CPU_RXD15_N
N19	HT_CPU_RXD14_N
N20	HT_CPU_RXD14_P
N21	HT_CPU_RXD7_N
N22	HT_CPU_RXD7_P
P1	PE0_TX4_P
P2	PE0_TX4_N
P3	PE0_RX9_P
P4	PE0_RX9_N
P6	PE_GND
P8	PE_GND
P9	+1.2V_PLLCORE
P11	GND
P12	GND
P13	GND
P14	GND
P16	HT_CPU_RXD13_P
P17	HT_CPU_RXD13_N
P19	GND
P21	HT_CPU_RXD6_N
P22	HT_CPU_RXD6_P
P23	HT_CPU_RXD5_N
P24	HT_CPU_RXD5_P
R1	PE0_TX5_P
R2	PE0_TX5_N
R3	PE0_TX6_P
R4	PE0_TX7_P
R5	PE0_RX8_N

Ball	Signal Name
R6	PE0_RX8_P
R7	PE0_RX10_N
R8	PE0_RX10_P
R9	+1.2V_PLLGPU
R16	+1.2V_HT
R17	GND
R18	HT_CPU_RXD12_P
R19	HT_CPU_RXD12_N
R20	HT_CPU_RX_CLK1_N
R21	HT_CPU_RX_CLK1_P
R22	GND
R23	HT_CPU_RXD4_N
R24	HT_CPU_RXD4_P
T2	PE0_TX6_N
T3	PE0_TX7_N
T4	PE_GND
T6	PE_GND
T8	PE0_RX12_P
T9	PE0_RX12_N
T10	HT_MCP_RX_CLK1_N
T11	+1.2V_PLLPE
T12	GND
T13	+1.2V_PLLHTMCP
T14	GND
T15	+1.2V_HTMCP
T16	+1.2V_HT
T17	GND
T19	GND
T21	HT_CPU_RXD11_P
T22	HT_CPU_RX_CLK0_N
T23	HT_CPU_RX_CLK0_P
U3	PE0_TX8_N
U4	PE0_TX8_P
U5	PE0_RX11_N
U6	PE0_RX11_P
U7	PE0_RX13_P
U8	PE0_RX13_N
U9	PE_GND
U10	HT_MCP_RX_CLK1_P
U11	+1.2V_HTMCP
U12	GND

PROPRIETARY INFORMATION

Ball	Signal Name
U13	+1.2V_HTMCP
U14	GND
U15	+1.2V_HTMCP
U16	+1.2V_HTMCP
U17	+1.2V_HT
U18	GND
U19	GND
U20	HT_CPU_RXD11_N
U21	HT_CPU_RXD3_N
U22	HT_CPU_RXD3_P
V1	PE0_TX9_P
V2	PE0_TX9_N
V3	PE0_RX14_N
V4	PE0_RX14_P
V6	PE_GND
V8	PE_GND
V9	HT_MCP_RXD11_P
V11	HT_MCP_RXD14_P
V13	HT_MCP_RXD15_N
V15	HT_MCP_TXD12_N
V17	HT_MCP_TXD11_N
V19	GND
V21	HT_CPU_RXD9_P
V22	GND
V23	HT_CPU_RXD2_N
V24	HT_CPU_RXD2_P
W1	PE0_TX10_P
W2	PE0_TX10_N
W3	PE0_TX11_P
W4	PE_GND
W5	CLKIN_200MHZ_N
W6	PE_GND
W7	HT_MCP_RXD9_P
W8	PE_GND
W9	HT_MCP_RXD11_N
W10	HT_MCP_RXD12_N
W11	HT_MCP_RXD14_N
W12	HT_MCP_RXD15_P
W13	HT_MCP_TXD15_P
W14	HT_MCP_TXD14_N
W15	HT_MCP_TXD12_P

Ball	Signal Name
W16	+1.2V_HTMCP
W17	HT_MCP_TX_CLK1_N
W18	HT_MCP_TXD11_P
W19	HT_CPU_CAL_1P2V
W20	HT_CPU_RXD9_N
W21	HT_CPU_RXD10_P
W22	HT_CPU_RXD10_N
W23	HT_CPU_RXD1_N
W24	HT_CPU_RXD1_P
Y2	PE0_TX11_N
Y3	PE0_RX15_P
Y4	PE_GND
Y5	CLKIN_200MHZ_P
Y6	HT_MCP_RXD8_N
Y7	HT_MCP_RXD9_N
Y8	HT_MCP_RXD10_P
Y9	+1.2V_HTMCP
Y10	HT_MCP_RXD12_P
Y11	GND
Y12	HT_MCP_RXD13_N
Y13	HT_MCP_TXD15_N
Y14	HT_MCP_TXD14_P
Y15	HT_MCP_TXD13_N
Y16	GND
Y17	HT_MCP_TX_CLK1_P
Y18	GND
Y19	HT_CPU_CAL_GND
Y20	HT_CPU_RXD8_N
Y21	HT_CPU_RXD8_P
Y22	HT_CPU_RXD0_N
Y23	HT_CPU_RXD0_P
AA1	PE0_TX12_P
AA2	PE0_TX12_N
AA3	PE0_RX15_N
AA4	GND
AA5	HT_MCP_STOP#
AA6	HT_MCP_RXD8_P
AA7	HT_MCP_RXD10_N
AA8	HT_MCP_RXD2_P
AA9	HT_MCP_RXD3_P
AA11	HT_MCP_RXD13_P

Ball	Signal Name
AA13	GND
AA15	HT_MCP_TXD13_P
AA17	HT_MCP_TXD5_P
AA18	+1.2V_HTMCP
AA19	HT_MCP_TXD10_N
AA20	HT_MCP_TXD9_N
AA21	GND
AA22	GND
AA23	GND
AA24	GND
AB1	PE0_TX13_P
AB2	PE0_TX13_N
AB3	PE_REFCLKIN_N
AB4	GND
AB5	HT_MCP_REQ#
AB6	GND
AB7	HT_MCP_RXD1_N
AB8	HT_MCP_RXD2_N
AB9	HT_MCP_RXD3_N
AB10	GND
AB11	+1.2V_HTMCP
AB12	HT_MCP_RXD6_N
AB13	HT_MCP_RXD7_N
AB14	GND
AB15	HT_MCP_TXD6_N
AB16	HT_MCP_TXD6_P
AB17	HT_MCP_TXD5_N
AB18	HT_MCP_TXD4_P
AB19	HT_MCP_TXD10_P
AB20	HT_MCP_TXD9_P
AB21	HT_MCP_TXD8_P
AB22	HT_MCP_TXD8_N
AB23	HT_MCP_CAL_1P2V
AB24	HT_MCP_CAL_GND
AC1	PE0_TX14_P
AC2	PE0_TX14_N
AC3	PE_REFCLKIN_P
AC4	CLKIN_25MHZ
AC5	HT_MCP_RESET#
AC6	HT_MCP_RXD0_N
AC7	HT_MCP_RXD1_P

PROPRIETARY INFORMATION

Ball	Signal Name
AC9	HT_MCP_RX_CLK0_N
AC10	HT_MCP_RXD4_N
AC11	HT_MCP_RXD5_N
AC12	HT_MCP_RXD6_P
AC13	HT_MCP_RXD7_P
AC14	HT_MCP_RXCTL_N
AC15	HT_MCP_TXCTL_P
AC16	HT_MCP_TXD7_P
AC18	HT_MCP_TXD4_N
AC19	HT_MCP_TX_CLK0_P

Ball	Signal Name
AC20	HT_MCP_TXD3_P
AC21	HT_MCP_TXD2_N
AC22	HT_MCP_TXD2_P
AC23	HT_MCP_TXD0_N
AC24	HT_MCP_TXD0_P
AD2	PE0_TX15_P
AD3	PE0_TX15_N
AD5	HT_MCP_PWRGD
AD6	HT_MCP_RXD0_P
AD9	HT_MCP_RX_CLK0_P

Ball	Signal Name
AD10	HT_MCP_RXD4_P
AD11	HT_MCP_RXD5_P
AD14	HT_MCP_RXCTL_P
AD15	HT_MCP_TXCTL_N
AD16	HT_MCP_TXD7_N
AD19	HT_MCP_TX_CLK0_N
AD20	HT_MCP_TXD3_n
AD22	HT_MCP_TXD1_N
AD23	HT_MCP_TXD11_P

PROPRIETARY INFORMATION

Table 33. Ball Listing by Signal Name

Signal Name	Ball
+1.2V_CORE	B5
+1.2V_CORE	C6
+1.2V_CORE	D7
+1.2V_CORE	E8
+1.2V_CORE	E9
+1.2V_CORE	E10
+1.2V_CORE	F10
+1.2V_CORE	F11
+1.2V_CORE	G11
+1.2V_CORE	H11
+1.2V_CORE	J11
+1.2V_CORE	J12
+1.2V_CORE	J13
+1.2V_CORE	J14
+1.2V_HT	K16
+1.2V_HT	M16
+1.2V_HT	R16
+1.2V_HT	M21
+1.2V_HT	J20
+1.2V_HT	T16
+1.2V_HT	U17
+1.2V_HT	C21
+1.2V_HT	H17
+1.2V_HTMCP	Y9
+1.2V_HTMCP	U11
+1.2V_HTMCP	AB11
+1.2V_HTMCP	U13
+1.2V_HTMCP	T15
+1.2V_HTMCP	U15
+1.2V_HTMCP	U16
+1.2V_HTMCP	W16
+1.2V_HTMCP	AA18
+1.2V_PEA	A3
+1.2V_PEA	B3
+1.2V_PEA	C4
+1.2V_PEA	D5
+1.2V_PEA	E6
+1.2V_PEA	F7
+1.2V_PEA	F8

Signal Name	Ball
+1.2V_PEA	F9
+1.2V_PED	B4
+1.2V_PLL	B2
+1.2V_PLL	C2
+1.2V_PLL	C3
+1.2V_PLL	D4
+1.2V_PLL	E5
+1.2V_PLL	F6
+1.2V_PLL	G7
+1.2V_PLL	G8
+1.2V_PED	C5
+1.2V_PED	D6
+1.2V_PED	E7
+1.2V_PLL	A2
+1.2V_PLL	G9
+1.2V_PLL	H10
+1.2V_PLL	J10
+1.2V_PLLCORE	P9
+1.2V_PLLGPU	R9
+1.2V_PLLHTCPU	N16
+1.2V_PLLHTMCP	T13
+1.2V_PLLIFP	H16
+1.2V_PLLPE	T11
+2.5V_CORE	C16
+2.5V_CORE	B16
+2.5V_IFPA	G15
+2.5V_IFPB	H15
+2.5V_PLLCORE	H12
+2.5V_PLLGPU	H13
+2.5V_PLLHTCPU	L16
+2.5V_PLLIFP	E16
+3.3V	C10
+3.3V	D18
+3.3V_DAC	A9
CLKIN_25MHZ	AC4
CLKOUT_CTERM_GND	B22
CLKOUT_PRI_200MHZ_N	B23

Signal Name	Ball
CLKOUT_PRI_200MHZ_P	B24
CLKOUT_SEC_200MHZ_N	B21
CLKOUT_SEC_200MHZ_P	A22
DAC_BLUE	A6
DAC_GREEN	B6
DAC_HSYNC	B7
DAC_IDUMP	C8
DAC_RED	A5
DAC_RSET	D8
DAC_VREF	D9
DAC_VSYNC	C7
GND	C1
GND	AA21
GND	AA13
GND	U14
GND	H14
GND	C11
GND	AB4
GND	AA4
GND	J15
GND	E12
GND	AB10
GND	Y18
GND	E18
GND	U18
GND	E15
GND	Y11
GND	U19
GND	N17
GND	F16
GND	J17
GND	L13
GND	B1
GND	T17
GND	D11
GND	T12

PROPRIETARY INFORMATION

Signal Name	Ball
GND	J16
GND	D19
GND	H19
GND	L21
GND	M19
GND	P19
GND	T19
GND	V19
GND	T14
GND	C20
GND	R17
GND	AB14
GND	U12
GND	G13
GND	Y16
GND	H21
GND	C22
GND	AB6
GND	F22
GND	L22
GND	R22
GND	V22
GND	AA22
GND	A23
GND	AA23
GND	AA24
GND	L11
GND	M11
GND	N11
GND	P11
GND	M12
GND	N12
GND	P12
GND	M13
GND	N13
GND	P13
GND	M14
GND	N14
GND	P14
GND	L14
GND	L12

Signal Name	Ball
HT_CPU_CAL_1P2V	W19
HT_CPU_CAL_GND	Y19
HT_CPU_PWRGD	E19
HT_CPU_REQ#	F18
HT_CPU_RESET#	D20
HT_CPU_RX_CLK0_N	T22
HT_CPU_RX_CLK0_P	T23
HT_CPU_RX_CLK1_N	R20
HT_CPU_RX_CLK1_P	R21
HT_CPU_RXCTL_N	M22
HT_CPU_RXCTL_P	M23
HT_CPU_RXD0_N	Y22
HT_CPU_RXD0_P	Y23
HT_CPU_RXD1_N	W23
HT_CPU_RXD1_P	W24
HT_CPU_RXD2_N	V23
HT_CPU_RXD2_P	V24
HT_CPU_RXD3_N	U21
HT_CPU_RXD3_P	U22
HT_CPU_RXD4_N	R23
HT_CPU_RXD4_P	R24
HT_CPU_RXD5_N	P23
HT_CPU_RXD5_P	P24
HT_CPU_RXD6_N	P21
HT_CPU_RXD6_P	P22
HT_CPU_RXD7_N	N21
HT_CPU_RXD7_P	N22
HT_CPU_RXD8_N	Y20
HT_CPU_RXD8_P	Y21
HT_CPU_RXD9_N	W20
HT_CPU_RXD9_P	V21
HT_CPU_RXD10_N	W22
HT_CPU_RXD10_P	W21
HT_CPU_RXD11_N	U20
HT_CPU_RXD11_P	T21
HT_CPU_RXD12_N	R19
HT_CPU_RXD12_P	R18
HT_CPU_RXD13_N	P17
HT_CPU_RXD13_P	P16
HT_CPU_RXD14_N	N19
HT_CPU_RXD14_P	N20

Signal Name	Ball
HT_CPU_RXD15_N	N18
HT_CPU_RXD15_P	M17
HT_CPU_STOP#	G18
HT_CPU_TX_CLK0_N	G24
HT_CPU_TX_CLK0_P	G23
HT_CPU_TX_CLK1_N	G21
HT_CPU_TX_CLK1_P	G22
HT_CPU_TXCTL_N	L24
HT_CPU_TXCTL_P	L23
HT_CPU_TXD0_N	C24
HT_CPU_TXD0_P	C23
HT_CPU_TXD1_N	D24
HT_CPU_TXD1_P	D23
HT_CPU_TXD2_N	E23
HT_CPU_TXD2_P	E22
HT_CPU_TXD3_N	F24
HT_CPU_TXD3_P	F23
HT_CPU_TXD4_N	H23
HT_CPU_TXD4_P	H22
HT_CPU_TXD5_N	J22
HT_CPU_TXD5_P	J21
HT_CPU_TXD6_N	K22
HT_CPU_TXD6_P	K21
HT_CPU_TXD7_N	K24
HT_CPU_TXD7_P	K23
HT_CPU_TXD8_N	D22
HT_CPU_TXD8_P	D21
HT_CPU_TXD9_N	E20
HT_CPU_TXD9_P	F19
HT_CPU_TXD10_N	E21
HT_CPU_TXD10_P	F21
HT_CPU_TXD11_N	G19
HT_CPU_TXD11_P	G20
HT_CPU_TXD12_N	J18
HT_CPU_TXD12_P	J19
HT_CPU_TXD13_N	K17
HT_CPU_TXD13_P	L17
HT_CPU_TXD14_N	K19
HT_CPU_TXD14_P	L20
HT_CPU_TXD15_N	L19
HT_CPU_TXD15_P	L18

PROPRIETARY INFORMATION

Signal Name	Ball
HT_MCP_CAL_1P2V	AB23
HT_MCP_CAL_GND	AB24
HT_MCP_PWRGD	AD5
HT_MCP_REQ#	AB5
HT_MCP_RESET#	AC5
HT_MCP_RX_CLK0_N	AC9
HT_MCP_RX_CLK0_P	AD9
HT_MCP_RX_CLK1_N	T10
HT_MCP_RX_CLK1_P	U10
HT_MCP_RXCTL_N	AC14
HT_MCP_RXCTL_P	AD14
HT_MCP_RXD0_N	AC6
HT_MCP_RXD0_P	AD6
HT_MCP_RXD1_N	AB7
HT_MCP_RXD1_P	AC7
HT_MCP_RXD2_N	AB8
HT_MCP_RXD2_P	AA8
HT_MCP_RXD3_N	AB9
HT_MCP_RXD3_P	AA9
HT_MCP_RXD4_N	AC10
HT_MCP_RXD4_P	AD10
HT_MCP_RXD5_N	AC11
HT_MCP_RXD5_P	AD11
HT_MCP_RXD6_N	AB12
HT_MCP_RXD6_P	AC12
HT_MCP_RXD7_N	AB13
HT_MCP_RXD7_P	AC13
HT_MCP_RXD8_N	Y6
HT_MCP_RXD8_P	AA6
HT_MCP_RXD9_N	Y7
HT_MCP_RXD9_P	W7
HT_MCP_RXD10_N	AA7
HT_MCP_RXD10_P	Y8
HT_MCP_RXD11_N	W9
HT_MCP_RXD11_P	V9
HT_MCP_RXD12_N	W10
HT_MCP_RXD12_P	Y10
HT_MCP_RXD13_N	Y12
HT_MCP_RXD13_P	AA11
HT_MCP_RXD14_N	W11
HT_MCP_RXD14_P	V11

Signal Name	Ball
HT_MCP_RXD15_N	V13
HT_MCP_RXD15_P	W12
HT_MCP_STOP#	AA5
HT_MCP_TX_CLK0_N	AD19
HT_MCP_TX_CLK0_P	AC19
HT_MCP_TX_CLK1_N	W17
HT_MCP_TX_CLK1_P	Y17
HT_MCP_TXCTL_N	AD15
HT_MCP_TXCTL_P	AC15
HT_MCP_TXD0_N	AC23
HT_MCP_TXD0_P	AC24
HT_MCP_TXD1_N	AD22
HT_MCP_TXD1_P	AD23
HT_MCP_TXD2_N	AC21
HT_MCP_TXD2_P	AC22
HT_MCP_TXD3_N	AD20
HT_MCP_TXD3_P	AC20
HT_MCP_TXD4_N	AC18
HT_MCP_TXD4_P	AB18
HT_MCP_TXD5_N	AB17
HT_MCP_TXD5_P	AA17
HT_MCP_TXD6_N	AB15
HT_MCP_TXD6_P	AB16
HT_MCP_TXD7_N	AD16
HT_MCP_TXD7_P	AC16
HT_MCP_TXD8_N	AB22
HT_MCP_TXD8_P	AB21
HT_MCP_TXD9_N	AA20
HT_MCP_TXD9_P	AB20
HT_MCP_TXD10_N	AA19
HT_MCP_TXD10_P	AB19
HT_MCP_TXD11_N	V17
HT_MCP_TXD11_P	W18
HT_MCP_TXD12_N	V15
HT_MCP_TXD12_P	W15
HT_MCP_TXD13_N	Y15
HT_MCP_TXD13_P	AA15
HT_MCP_TXD14_N	W14
HT_MCP_TXD14_P	Y14
HT_MCP_TXD15_N	Y13
HT_MCP_TXD15_P	W13

Signal Name	Ball
IFPA_TXC_N	B13
IFPA_TXC_P	C14
IFPA_TXD0_N	B15
IFPA_TXD0_P	A15
IFPA_TXD1_N	C15
IFPA_TXD1_P	D15
IFPA_TXD2_N	B14
IFPA_TXD2_P	A14
IFPA_TXD3_N	E14
IFPA_TXD3_P	F14
IFPAB_RSET	F15
IFPAB_VPROBE	A16
IFPB_TXC_N	B10
IFPB_TXC_P	A10
IFPB_TXD4_N	A11
IFPB_TXD4_P	B11
IFPB_TXD5_N	F13
IFPB_TXD5_P	E13
IFPB_TXD6_N	C13
IFPB_TXD6_P	D13
IFPB_TXD7_N	C12
IFPB_TXD7_P	B12
JTAG_TCK	C18
JTAG_TDI	B19
JTAG_TDO	C19
JTAG_TMS	B18
JTAG_TRST#	A19
NC	F12
NC	E11
NC	E17
NC	F17
NC	G17
PE_CTERM_GND	D2
PE_GND	F3
PE_GND	L9
PE_GND	P8
PE_GND	N9
PE_GND	K4
PE_GND	N4
PE_GND	T4
PE_GND	W4

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Signal Name	Ball
PE_GND	Y4
PE_GND	U9
PE_GND	V8
PE_GND	K6
PE_GND	M6
PE_GND	P6
PE_GND	T6
PE_GND	W6
PE_GND	W8
PE_GND	H8
PE_GND	K8
PE_GND	V6
PE_GND	F4
PE_GND	H9
PE_REFCLKIN_N	AB3
PE_REFCLKIN_P	AC3
PE_RESET#	G1
PE_TSTCLK_N	F2
PE_TSTCLK_P	F1
PE0_PRSENT#	D1
PE0_REFCLK_N	K2
PE0_REFCLK_P	K1
PE0_RX0_N	J7
PE0_RX0_P	J8
PE0_RX1_N	J5
PE0_RX1_P	J6
PE0_RX2_N	J9
PE0_RX2_P	K9
PE0_RX3_N	L5
PE0_RX3_P	L6
PE0_RX4_N	L8
PE0_RX4_P	L7
PE0_RX5_N	M8
PE0_RX5_P	M9
PE0_RX6_N	N7
PE0_RX6_P	N8
PE0_RX7_N	N5
PE0_RX7_P	N6
PE0_RX8_N	R5
PE0_RX8_P	R6
PE0_RX9_N	P4

Signal Name	Ball
PE0_RX9_P	P3
PE0_RX10_N	R7
PE0_RX10_P	R8
PE0_RX11_N	U5
PE0_RX11_P	U6
PE0_RX12_N	T9
PE0_RX12_P	T8
PE0_RX13_N	U8
PE0_RX13_P	U7
PE0_RX14_N	V3
PE0_RX14_P	V4
PE0_RX15_N	AA3
PE0_RX15_P	Y3
PE0_TX0_N	L2
PE0_TX0_P	L1
PE0_TX1_N	M2
PE0_TX1_P	L3
PE0_TX2_N	M3
PE0_TX2_P	L4
PE0_TX3_N	N3
PE0_TX3_P	M4
PE0_TX4_N	P2
PE0_TX4_P	P1
PE0_TX5_N	R2
PE0_TX5_P	R1
PE0_TX6_N	T2
PE0_TX6_P	R3
PE0_TX7_N	T3
PE0_TX7_P	R4
PE0_TX8_N	U3
PE0_TX8_P	U4
PE0_TX9_N	V2
PE0_TX9_P	V1
PE0_TX10_N	W2
PE0_TX10_P	W1
PE0_TX11_N	Y2
PE0_TX11_P	W3
PE0_TX12_N	AA2
PE0_TX12_P	AA1
PE0_TX13_N	AB2
PE0_TX13_P	AB1

Signal Name	Ball
PE0_TX14_N	AC2
PE0_TX14_P	AC1
PE0_TX15_N	AD3
PE0_TX15_P	AD2
PE1_CLKREQ#	D3
PE1_PRSENT#	E2
PE1_REFCLK_N	G3
PE1_REFCLK_P	G2
PE1_RX_N	H6
PE1_RX_P	G6
PE1_TX_N	G5
PE1_TX_P	G4
PE2_CLKREQ#	E4
PE2_PRSENT#	E3
PE2_REFCLK_N	H3
PE2_REFCLK_P	H2
PE2_RX_N	K3
PE2_RX_P	J4
PE2_TX_N	J3
PE2_TX_P	H4
PKG_TEST	D17
SCLKIN_MCLKOUT_200MHZ_N	B20
SCLKIN_MCLKOUT_200MHZ_P	A20
TEST_MODE_EN	C17
XTAL_IN	C9
XTAL_OUT	B9

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Appendix B. Ballout

This appendix contains the ballout for the NVIDIA C51M.

- Ball Locations

- Ballout (Top Left View)
- Ballout (Top Right View)

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Ballout (Top Left View)

Pin Define

	1	2	3	4	5	6	7	8	9	10	11	12
A		+1.2V_PLL	+1.2V_PEA		DAC_RED	DAC_BLUE			+3.3V_DAC	IFPB_TXC_P	IFPB_TXD4_N	
B	GND	+1.2V_PLL	+1.2V_PEA	+1.2V_PED	+1.2V_CORE	DAC_GREEN	DAC_HSYNC		XTAL_OUT	IFPB_TXC_N	IFPB_TXD4_P	IFPB_TXD7_P
C	GND	+1.2V_PLL	+1.2V_PLL	+1.2V_PEA	+1.2V_PED	+1.2V_CORE	DAC_VSYNC	DAC_IDUMP	XTAL_IN	+3.3V	GND	IFPB_TXD7_N
D	PE0_PRSN#	PE_CTERM_GND	PE1_CLKREQ#	+1.2V_PLL	+1.2V_PEA	+1.2V_PED	+1.2V_CORE	DAC_RSET	DAC_VREF		GND	
E		PE1_PRSN#	PE2_PRSN#	PE2_CLKREQ#	+1.2V_PLL	+1.2V_PEA	+1.2V_PED	+1.2V_CORE	+1.2V_CORE	+1.2V_CORE	NC	GND
F	PE_TSTCLK_P	PE_TSTCLK_N	PE_GND	PE_GND		+1.2V_PLL	+1.2V_PEA	+1.2V_PEA	+1.2V_PEA	+1.2V_CORE	+1.2V_CORE	NC
G	PE_RESET#	PE1_REFCLK_P	PE1_REFCLK_N	PE1_TX_P	PE1_TX_N	PE1_RX_P	+1.2V_PLL	+1.2V_PLL	+1.2V_PLL		+1.2V_CORE	
H		PE2_REFCLK_P	PE2_REFCLK_N	PE2_TX_P		PE1_RX_N		PE_GND	PE_GND	+1.2V_PLL	+1.2V_CORE	+2.5V_PLLCORE
J			PE2_TX_N	PE2_RX_P	PE0_RX1_N	PE0_RX1_P	PE0_RX0_N	PE0_RX0_P	PE0_RX2_N	+1.2V_PLL	+1.2V_CORE	+1.2V_CORE
K	PE0_REFCLK_P	PE0_REFCLK_N	PE2_RX_N	PE_GND		PE_GND		PE_GND	PE0_RX2_P			
L	PE0_TX0_P	PE0_TX0_N	PE0_TX1_P	PE0_TX2_P	PE0_RX3_N	PE0_RX3_P	PE0_RX4_P	PE0_RX4_N	PE_GND		GND	GND
M		PE0_TX1_N	PE0_TX2_N	PE0_TX3_P		PE_GND		PE0_RX5_N	PE0_RX5_P		GND	GND
N			PE0_TX3_N	PE_GND	PE0_RX7_N	PE0_RX7_P	PE0_RX6_N	PE0_RX6_P	PE_GND		GND	GND
P	PE0_TX4_P	PE0_TX4_N	PE0_RX9_P	PE0_RX9_N		PE_GND		PE_GND	+1.2V_PLLCORE		GND	GND
R	PE0_TX5_P	PE0_TX5_N	PE0_TX6_P	PE0_TX7_P	PE0_RX8_N	PE0_RX8_P	PE0_RX10_N	PE0_RX10_P	+1.2V_PLGPU			
T		PE0_TX6_N	PE0_TX7_N	PE_GND		PE_GND		PE0_RX12_P	PE0_RX12_N	HT_MCP_RX_CLK1_N	+1.2V_PLPE	GND
U			PE0_TX8_N	PE0_TX8_P	PE0_RX11_N	PE0_RX11_P	PE0_RX13_P	PE0_RX13_N	PE_GND	HT_MCP_RX_CLK1_P	+1.2V_HTMCP	GND
V	PE0_TX9_P	PE0_TX9_N	PE0_RX14_N	PE0_RX14_P		PE_GND		PE_GND	HT_MCP_RXD11_P		HT_MCP_RXD14_P	
W	PE0_TX10_P	PE0_TX10_N	PE0_TX11_P	PE_GND	CLKIN_200MHZ_N	PE_GND	HT_MCP_RXD9_P	PE_GND	HT_MCP_RXD11_N	HT_MCP_RXD12_N	HT_MCP_RXD14_N	HT_MCP_RXD15_P
Y		PE0_TX11_N	PE0_RX15_P	PE_GND	CLKIN_200MHZ_P	HT_MCP_RXD8_N	HT_MCP_RXD9_N	HT_MCP_RXD10_P	+1.2V_HTMCP	HT_MCP_RXD12_P	GND	HT_MCP_RXD13_N
AA	PE0_TX12_P	PE0_TX12_N	PE0_RX15_N	GND	HT_MCP_STOP#	HT_MCP_RXD8_P	HT_MCP_RXD10_N	HT_MCP_RXD2_P	HT_MCP_RXD3_P		HT_MCP_RXD13_P	
AB	PE0_TX13_P	PE0_TX13_N	PE_REFCLKIN_N	GND	HT_MCP_REQ#	GND	HT_MCP_RXD1_N	HT_MCP_RXD2_N	HT_MCP_RXD3_N	GND	+1.2V_HTMCP	HT_MCP_RXD6_N
AC	PE0_TX14_P	PE0_TX14_N	PE_REFCLKIN_P	CLKIN_25MHZ	HT_MCP_RESET#	HT_MCP_RXD0_N	HT_MCP_RXD1_P		HT_MCP_RX_CLK0_N	HT_MCP_RXD4_N	HT_MCP_RXD5_N	HT_MCP_RXD6_P
AD		PE0_TX15_P	PE0_TX15_N		HT_MCP_PWRGD	HT_MCP_RXD0_P			HT_MCP_RX_CLK0_P	HT_MCP_RXD4_P	HT_MCP_RXD5_P	
	1	2	3	4	5	6	7	8	9	10	11	12

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Ballout (Top Right View)

13	14	15	16	17	18	19	20	21	22	23	24	
	IFPA_TXD2_P	IFPA_TXD0_P	IFPAB_VPROBE			JTAG_TRST#	SCLKIN_MCLKOUT_200MHZ_P		CLKOUT_SEC_200MHZ_P	GND		A
IFPA_TXC_N	IFPA_TXD2_N	IFPA_TXD0_N	+2.5V_CORE		JTAG_TMS	JTAG_TDI	SCLKIN_MCLKOUT_200MHZ_N	CLKOUT_SEC_200MHZ_N	CLKOUT_CTERM_GND	CLKOUT_PRI_200MHZ_N	CLKOUT_PRI_200MHZ_P	B
IFPB_TXD6_N	IFPA_TXC_P	IFPA_TXD1_N	+2.5V_CORE	TEST_MODE_EN	JTAG_TCK	JTAG_TDO	GND	+1.2V_HT	GND	HT_CPU_TXD0_P	HT_CPU_TXD0_N	C
IFPB_TXD6_P		IFPA_TXD1_P		PKG_TEST	+3.3V	GND	HT_CPU_RESET#	HT_CPU_TXD8_P	HT_CPU_TXD8_N	HT_CPU_TXD1_P	HT_CPU_TXD1_N	D
IFPB_TXD5_P	IFPA_TXD3_N	GND	+2.5V_PLLIFP	NC	GND	HT_CPU_PWRGD	HT_CPU_TXD9_N	HT_CPU_TXD10_N	HT_CPU_TXD2_P	HT_CPU_TXD2_N		E
IFPB_TXD5_N	IFPA_TXD3_P	IFPAB_RSET	GND	NC	HT_CPU_REQ#	HT_CPU_TXD9_P		HT_CPU_TXD10_P	GND	HT_CPU_TXD3_P	HT_CPU_TXD3_N	F
GND		+2.5V_IFPA		NC	HT_CPU_STOP#	HT_CPU_TXD11_N	HT_CPU_TXD11_P	HT_CPU_TX_CLK1_N	HT_CPU_TX_CLK1_P	HT_CPU_TX_CLK0_P	HT_CPU_TX_CLK0_N	G
+2.5V_PLLGPU	GND	+2.5V_IFPB	+1.2V_PLLIFP	+1.2V_HT		GND		GND	HT_CPU_TXD4_P	HT_CPU_TXD4_N		H
+1.2V_CORE	+1.2V_CORE	GND	GND	GND	HT_CPU_TXD12_N	HT_CPU_TXD12_P	+1.2V_HT	HT_CPU_TXD5_P	HT_CPU_TXD5_N			J
			+1.2V_HT	HT_CPU_TXD13_N		HT_CPU_TXD14_N		HT_CPU_TXD6_P	HT_CPU_TXD6_N	HT_CPU_TXD7_P	HT_CPU_TXD7_N	K
GND	GND		+2.5V_PLLHTCPU	HT_CPU_TXD13_P	HT_CPU_TXD15_P	HT_CPU_TXD15_N	HT_CPU_TXD14_P	GND	GND	HT_CPU_TXCTL_P	HT_CPU_TXCTL_N	L
GND	GND		+1.2V_HT	HT_CPU_RXD15_P		GND		+1.2V_HT	HT_CPU_RXCTL_N	HT_CPU_RXCTL_P		M
GND	GND		+1.2V_PLLHTCPU	GND	HT_CPU_RXD15_N	HT_CPU_RXD14_N	HT_CPU_RXD14_P	HT_CPU_RXD7_N	HT_CPU_RXD7_P			N
GND	GND		HT_CPU_RXD13_P	HT_CPU_RXD13_N		GND		HT_CPU_RXD6_N	HT_CPU_RXD6_P	HT_CPU_RXD5_N	HT_CPU_RXD5_P	P
			+1.2V_HT	GND	HT_CPU_RXD12_P	HT_CPU_RXD12_N	HT_CPU_RX_CLK1_N	HT_CPU_RX_CLK1_P	GND	HT_CPU_RXD4_N	HT_CPU_RXD4_P	R
+1.2V_PLLHTMCP	GND	+1.2V_HTMCP	+1.2V_HT	GND		GND		HT_CPU_RXD11_P	HT_CPU_RX_CLK0_N	HT_CPU_RX_CLK0_P		T
+1.2V_HTMCP	GND	+1.2V_HTMCP	+1.2V_HTMCP	+1.2V_HT	GND	GND	HT_CPU_RXD11_N	HT_CPU_RXD3_N	HT_CPU_RXD3_P			U
HT_MCP_RXD15_N		HT_MCP_TXD12_N		HT_MCP_TXD11_N		GND		HT_CPU_RXD9_P	GND	HT_CPU_RXD2_N	HT_CPU_RXD2_P	V
HT_MCP_TXD15_P	HT_MCP_TXD14_N	HT_MCP_TXD12_P	+1.2V_HTMCP	HT_MCP_TX_CLK1_N	HT_MCP_TXD11_P	HT_CPU_CAL_1P2V	HT_CPU_RXD9_N	HT_CPU_RXD10_P	HT_CPU_RXD10_N	HT_CPU_RXD1_N	HT_CPU_RXD1_P	W
HT_MCP_TXD15_N	HT_MCP_TXD14_P	HT_MCP_TXD13_N	GND	HT_MCP_TX_CLK1_P	GND	HT_CPU_CAL_GND	HT_CPU_RXD8_N	HT_CPU_RXD8_P	HT_CPU_RXD0_N	HT_CPU_RXD0_P		Y
GND		HT_MCP_TXD13_P		HT_MCP_TXD5_P	+1.2V_HTMCP	HT_MCP_TXD10_N	HT_MCP_TXD9_N	GND	GND	GND	GND	AA
HT_MCP_RXD7_N	GND	HT_MCP_TXD6_N	HT_MCP_TXD6_P	HT_MCP_TXD5_N	HT_MCP_TXD4_P	HT_MCP_TXD10_P	HT_MCP_TXD9_P	HT_MCP_TXD8_P	HT_MCP_TXD8_N	HT_MCP_CAL_1P2V	HT_MCP_CAL_GND	AB
HT_MCP_RXD7_P	HT_MCP_RXCTL_N	HT_MCP_TXCTL_P	HT_MCP_TXD7_P		HT_MCP_TXD4_N	HT_MCP_TX_CLK0_P	HT_MCP_TXD3_P	HT_MCP_TXD2_N	HT_MCP_TXD2_P	HT_MCP_TXD0_N	HT_MCP_TXD0_P	AC
	HT_MCP_RXCTL_P	HT_MCP_TXCTL_N	HT_MCP_TXD7_N			HT_MCP_TX_CLK0_N	HT_MCP_TXD3_N		HT_MCP_TXD1_N	HT_MCP_TXD1_P		AD
13	14	15	16	17	18	19	20	21	22	23	24	

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